

General Description



Note: Images are for illustrative purposes only; actual products may differ.

BDE-MP2674R10 is a high-performance multiprotocol 2.4-GHz wireless module series based on Texas Instruments (TI)'s multiprotocol wireless microcontroller (MCU) CC2674R106T0RGZR. In order to fulfil different integration scenarios, BDE provides different variants for this module series. They are listed and described in [Table 1](#).

BDE-MP2674R10 module series integrates a powerful 48-MHz Arm® Cortex®-M33 MCU, which supports Thread, Zigbee®, Matter, Bluetooth® 5.2 Low Energy, IEEE 802.15.4g, IPv6-enabled smart objects (6LoWPAN), proprietary systems including TI 15.4-Stack (2.4-GHz), and concurrent multiprotocol through a Dynamic Multiprotocol Manager (DMM) driver. The device is optimized for low-power wireless communication and advanced sensing in building security systems, HVAC, medical, wired networking, portable electronics, and home theater & entertainment markets.

BDE-MP2674R10 module series can support +5 dBm output power setting and a receive sensitivity of -103 dBm for 125-kbps Bluetooth® Low Energy Coded PHY. It is with low standby current of 0.92 μ A with full 256 KB RAM retention that enables longer battery life wireless applications. The module series supports for ARM® TrustZone® based secure key storage, device ID and trusted functions; Low SER (Soft Error Rate) FIT (Failure-in-time) for long operational lifetime with no disruption for industrial markets with always-on SRAM parity against corruption due to potential radiation events. The device also has an autonomous ultra-low power Sensor Controller CPU with fast wake-up capability. As an example, the sensor controller is capable of 1-Hz ADC sampling at 1- μ A system current.

BDE-MP2674R10 module series integrates all required system-level hardware components including clocks, balun filter, other passives, and PCB trace antenna or U.FL connector into a small PCB form factor. It is for easy assembly and low-cost PCB design. It can work standalone without using an external MCU. With its best-in-class radio performance, ultra-low power, small form factor and low cost, the BDE-MP2674R10 module series is the best choice for the applications that are sensitive to power consumption, size and cost.

Table 1. Module Variants

Part Number	Antenna Type	Integrated On-board SPI Flash (Mbit)	Operating Temperature
BDE-MP2674R10A32	PCB trace antenna	32	-40°C to +85°C
BDE-MP2674R10U32	U.FL connector		
BDE-MP2674R10N32	ANT pin		
BDE-MP2674R10A0	PCB trace antenna	0	
BDE-MP2674R10U0	U.FL connector		
BDE-MP2674R10N0	ANT pin		
BDE-MP2674R10A32-IN	PCB trace antenna	32	-40°C to +105°C
BDE-MP2674R10U32-IN	U.FL connector		

Part Number	Antenna Type	Integrated On-board SPI Flash (Mbit)	Operating Temperature
BDE-MP2674R10N32-IN	ANT pin	0	
BDE-MP2674R10A0-IN	PCB trace antenna		
BDE-MP2674R10U0-IN	U.FL connector		
BDE-MP2674R10N0-IN	ANT pin		

Key Features

■ Wireless microcontroller

- Powerful 48-MHz Arm® Cortex®- M33 processor with TrustZone®
- FPU and DSP extension
- 1024 KB flash program memory
- 8 KB of cache SRAM
- 256 KB of ultra-low leakage SRAM with parity for high-reliability operation
 - ✧ 32 KB of additional SRAM is available if parity is disabled
- Dynamic multiprotocol manager (DMM) driver
- Programmable radio includes support for 2-(G)FSK, 4-(G)FSK, MSK, Bluetooth® 5.2 Low Energy, IEEE 802.15.4 PHY and MAC
- Supports over-the-air upgrade (OTA)

■ Ultra-low power sensor controller

- Autonomous MCU with 4 KB of SRAM
- Sample, store, and process sensor data
- Fast wake-up for low-power operation
- Software defined peripherals, capacitive touch, flow meter, LCD

■ Low power consumption

- MCU consumption:
 - ✧ 4.0 mA active mode, CoreMark®
 - ✧ 83 µA/MHz running CoreMark®
 - ✧ 1.19 µA standby mode, RTC, 256 KB RAM
 - ✧ 0.13 µA shutdown mode, wake-up on pin
- Ultra-low power sensor controller consumption:
 - ✧ 30 µA in 2 MHz mode
 - ✧ 809 µA in 24 MHz mode
- Radio consumption:
 - ✧ 6.4 mA RX
 - ✧ 7.3 mA TX at 0 dBm

■ Wireless protocol support

- Thread, Zigbee®, Matter
- Bluetooth® 5.2 Low Energy
- 6LoWPAN
- Proprietary systems

■ High performance radio

- +3 dBm TX power (+5 dBm setting)
- -103 dBm for Bluetooth® Low Energy 125-kbps

■ MCU peripherals

- Most digital peripherals can be routed to any GPIO
- Four 32-bit or eight 16-bit general-purpose timers
- 12-bit SAR ADC, 200 kSamples/s, 8 channels
- 8-bit DAC
- Two comparators
- Programmable current source
- Four UART, four SPI, two I²C, I²S
- Real-time clock (RTC)
- Integrated temperature and battery monitor
- 33 GPIOs – none SPI flash versions
- 29 GPIOs – SPI flash versions

■ Security enablers

- Supports secure boot
- Supports secure key storage and device ID
- Arm TrustZone for trusted execution environment
- AES 128- and 256-bit cryptographic accelerator
- ECC and RSA public key hardware accelerator
- SHA2 Accelerator (full suite up to SHA-512)
- True random number generator (TRNG)
- Secure debug lock
- Software anti-rollback protection

■ Operating range

- On-chip buck DC/DC converter
- 1.8 V to 3.8 V single supply voltage

- 2.3-V to 3.6-V single supply voltage (SPI flash variants)
- -40 to +85°C / -40 to +105°C

■ Antenna options

- Integrated PCB trace antenna
- U.FL connector for external antenna
- ANT pin out for external antenna

■ On-board SPI flash

- 32-Mbit, only available in SPI flash versions

■ Package

- Dimension: 21.5 mm x 15 mm x 2.15 mm
- LCC-36 – A variants
- LCC-39 – U and N variants

■ Certification

- FCC ID: 2ABRU-MP26R
- IC: 25657-MP26R
- CE-RED
- Bluetooth SIG

Applications

- 2400 to 2480 MHz ISM and SRD systems with down to 4 kHz of receive bandwidth

■ Building automation

- Building security systems – motion detector, electronic smart lock, door and window sensor, garage door system, gateway
- HVAC – thermostat, wireless environmental sensor, HVAC system controller, gateway
- Fire safety system – smoke and heat detector, fire alarm control panel (FACP)
- Video surveillance – IP network camera
- Elevators and escalators – elevator main control panel for elevators and escalators

■ Industrial transport – asset tracking**■ Factory automation and control****■ Medical**

- Personal care & fitness
- Patient monitoring & diagnostics – medical sensor patches, multiparameter patient monitor

- Medical equipment
- Home healthcare – blood glucose monitor, pulse oximeter

■ Electronic point of sale (EPOS) – Electronic Shelf Label (ESL)**■ Communication equipment****■ Wired networking – wireless LAN or Wi-Fi access points, edge router****■ Personal electronics**

- Portable electronics – RF smart remote control
- Home theater & entertainment – smart speakers, smart display, set-top box
- Connected peripherals – consumer wireless keypads
- Gaming – electronic and robotic toys
- Wearables (non-medical) – smart trackers, smart clothing

Module Family

Table 2. Module Family

Product Type & Series Name	Orderable Part Number	Chipset & Core	On-chip Flash Size (KB)	On-chip SRAM Size (KB)	Connectivity	Antenna Options	On-board SPI Flash (Mbit)	Operating Temp. (°C)	Size (mm)
Module BDE-MP26R	BDE-MP2674R10A32	CC2674R10 Cortex-M33	1024	296	2.4GHz BLE 5.2 & ZigBee & Thread	PCB trace antenna	32	-40 to +85	21.5 × 15 × 2.15
	BDE-MP2674R10U32					U.FL connector			
	BDE-MP2674R10N32					ANT pin			
	BDE-MP2674R10A0					PCB trace antenna	0		
	BDE-MP2674R10U0					U.FL connector			
	BDE-MP2674R10N0					ANT pin			
	BDE-MP2674R10A32-IN					PCB trace antenna	32	-40 to +105	
	BDE-MP2674R10U32-IN					U.FL connector			
	BDE-MP2674R10N32-IN					ANT pin			
	BDE-MP2674R10A0-IN					PCB trace antenna	0		
	BDE-MP2674R10U0-IN					U.FL connector			
	BDE-MP2674R10N0-IN					ANT pin			
	BDE-MP2652R7A32	CC2652R7 Coretex-M4F	704	152	2.4GHz BLE 5.2 & ZigBee & Thread	PCB trace antenna	32	-40 to +85	21.5 × 15 × 2.15
	BDE-MP2652R7U32					U.FL connector			
	BDE-MP2652R7N32					ANT pin			
	BDE-MP2652R7A0					PCB trace antenna	0		
	BDE-MP2652R7U0					U.FL connector			
	BDE-MP2652R7N0					ANT pin			
	BDE-MP2652R7A32-IN					PCB trace antenna	32	-40 to +105	
	BDE-MP2652R7U32-IN					U.FL connector			
	BDE-MP2652R7N32-IN					ANT pin			
	BDE-MP2652R7A0-IN					PCB trace antenna	0		
	BDE-MP2652R7U0-IN					U.FL connector			
	BDE-MP2652R7N0-IN					ANT pin			
	BDE-MP2652RA32	CC2652R Coretex-M4F	352	88	2.4GHz BLE 5.2 & ZigBee & Thread	PCB trace antenna	32	-40 to +85	21.5 × 15 × 2.15
	BDE-MP2652RU32					U.FL connector			
	BDE-MP2652RN32					ANT pin			
	BDE-MP2652RA0					PCB trace antenna	0		
	BDE-MP2652RU0					U.FL connector			
	BDE-MP2652RN0					ANT pin			
	BDE-MP2652RA32-IN					PCB trace antenna	32	-40 to +105	
	BDE-MP2652RU32-IN					U.FL connector			
	BDE-MP2652RN32-IN					ANT pin			
	BDE-MP2652RA0-IN					PCB trace antenna	0		
	BDE-MP2652RU0-IN					U.FL connector			

Product Type & Series Name	Orderable Part Number	Chipset & Core	On-chip Flash Size (KB)	On-chip SRAM Size (KB)	Connectivity	Antenna Options	On-board SPI Flash (Mbit)	Operating Temp. (°C)	Size (mm)
	BDE-MP2652RN0-IN					ANT pin			
	BDE-MP2651R3A32	CC2651R3 Cortex-M4	352	40	2.4GHz BLE 5.2 & ZigBee & Thread	PCB trace antenna	32	-40 to +85	21.5 × 15 × 2.15
	BDE-MP2651R3U32					U.FL connector			
	BDE-MP2651R3N32					ANT pin			
	BDE-MP2651R3A0					PCB trace antenna	0		
	BDE-MP2651R3U0					U.FL connector			
	BDE-MP2651R3N0					ANT pin			
	BDE-MP2651R3A32-IN					PCB trace antenna	32	-40 to +105	
	BDE-MP2651R3U32-IN					U.FL connector			
	BDE-MP2651R3N32-IN					ANT pin			
	BDE-MP2651R3A0-IN					PCB trace antenna	0		
	BDE-MP2651R3U0-IN					U.FL connector			
	BDE-MP2651R3N0-IN					ANT pin			
	BDE-MP2642RA32	CC2642R Coretex-M4F	352	88	2.4GHz BLE 5.2	PCB trace antenna	32	-40 to +85	21.5 × 15 × 2.15
	BDE-MP2642RU32					U.FL connector			
	BDE-MP2642RN32					ANT pin			
	BDE-MP2642RA0					PCB trace antenna	0		
	BDE-MP2642RU0					U.FL connector			
	BDE-MP2642RN0					ANT pin			
	BDE-MP2642RA32-IN					PCB trace antenna	32	-40 to +105	
	BDE-MP2642RU32-IN					U.FL connector			
	BDE-MP2642RN32-IN					ANT pin			
	BDE-MP2642RA0-IN					PCB trace antenna	0		
	BDE-MP2642RU0-IN					U.FL connector			
	BDE-MP2642RN0-IN					ANT pin			

Naming Convention

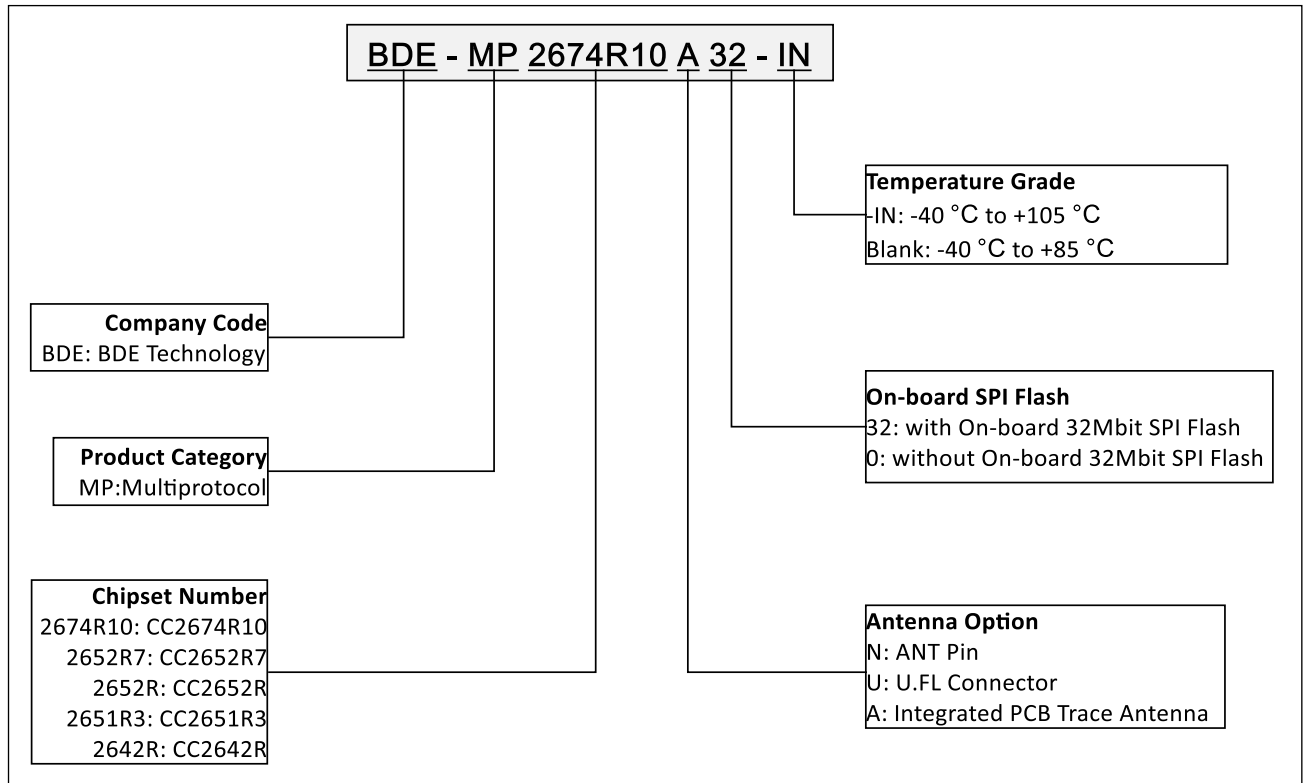


Figure 1. Module Naming Convention

Contents

General Description	1
Key Features.....	2
Applications	3
Module Family	4
Naming Convention	6
Contents.....	7
List of Tables.....	9
List of Figures	10
Reference	11
1. System Overview.....	12
1.1. Block Diagram	12
1.2. System CPU.....	14
1.3. Radio (RF Core)	14
1.3.1. Bluetooth 5.2 Low Energy	14
1.3.2. 802.15.4 Thread, Zigbee, and 6LoWPAN	15
1.4. Memory	15
1.5. Sensor Controller	15
1.6. Cryptography	16
1.7. Timer	17
1.8. Serial Peripherals and I/O	17
1.9. Battery and Temperature Monitor	17
1.10. μ DMA.....	18
1.11. Debug	18
1.12. Clock	18
1.13. Network Processor	18
1.14. Power Management	19
1.15. Antenna	20
2. Pinout Functions	21
2.1. Pinout Diagram	21
2.2. Pinout Descriptions	22
2.3. Connections for Unused Pins.....	23
3. Specifications	24
3.1. Electrical Characteristics	24
3.1.1. Absolute Maximum Ratings	24
3.1.2. ESD Ratings.....	24
3.1.3. Recommended Operating Conditions	24
3.1.4. Power Consumption	25
3.1.5. Clock Characteristics	26
3.1.6. Reset Timing.....	26
3.1.7. UART Characteristics	26
3.1.8. SPI Characteristics	26
3.1.9. GPIO DC Characteristics	27

3.1.10. ADC Characteristics	28
3.1.11. DAC Characteristics	28
3.1.12. Comparator Characteristics	29
3.2. RF Characteristics	29
3.2.1. BLE Performance: Receiver Characteristics	29
3.2.2. BLE Performance: Transmitter Characteristics	31
3.2.3. Zigbee Performance: Receiver Characteristics	31
3.2.4. Zigbee Performance: Transmitter Characteristics	32
3.3. Antenna Characteristics	32
3.3.1. Antenna Gain	33
3.3.2. Antenna Radiation Pattern	34
3.3.3. Other Certified Antennas	34
4. Mechanical Specifications	35
4.1. Dimensions	35
4.2. PCB Footprint	36
4.3. U.FL Connector Specification	38
5. Integration Guidelines	39
5.1. SoC Mode	39
5.2. WNP Mode	39
5.3. Module Placement	40
5.4. Other Design Considerations	40
5.1. Development Resources	41
6. Handling Instructions	42
6.1. Module Marking	42
6.2. Packaging Information	42
6.2.1. Tape and Reel Package Information	42
6.2.2. Carton Information and Labeling	44
6.3. Assembly Instruction	46
6.3.1. Moisture Sensitive Level	46
6.3.2. Reflow Profile	47
6.3.3. Other Consideration	47
7. Certification	48
7.1. Bluetooth Qualification	48
7.1.1. Bluetooth Qualification Information	48
7.1.2. Bluetooth Qualification Process	48
7.2. Regulatory Compliance	48
7.2.1. Certified Antennas	49
7.2.2. FCC Compliance	50
7.2.3. IC/ISED Compliance	51
7.2.4. ETSI/CE Compliance	52
8. Ordering Information	53
9. Revision History	54
Important Notice and Disclaimer	55
Contact	55

List of Tables

Table 1. Module Variants	1
Table 2. Module Family	4
Table 3. Power Mode	19
Table 4. Pin Description ⁽¹⁾	22
Table 5. Connections for Unused Pins	23
Table 6. Absolute Maximum Ratings	24
Table 7. ESD Ratings	24
Table 8. Recommended Operating Conditions	25
Table 9. Power Consumption—Power Modes	25
Table 10. Power Consumption—Radio Modes	26
Table 11. 48-MHz Crystal Oscillator (XOSC_HF) Characteristics	26
Table 12. 32.768-KHz Crystal Oscillator (XOSC_LF) Characteristics	26
Table 13. Reset Timing	26
Table 14. UART Characteristics	26
Table 15. SPI Characteristics	27
Table 16. GPIO DC Characteristics	27
Table 17. ADC Characteristics	28
Table 18. DAC Characteristics	28
Table 19. Low-Power Clocked Comparator	29
Table 20. Continuous Time Comparator	29
Table 21. Receive (RX) Characteristics—Bluetooth	29
Table 22. Transmit (TX) Characteristics—Bluetooth	31
Table 23. Receiver (RX) Characteristics—Zigbee Performance	31
Table 24. Transmit (TX) Characteristics—Zigbee Performance	32
Table 25. Gain of Integrated PCB Trace Antenna	33
Table 26. Other Design Considerations	41
Table 27. Reflow Profile Parameters ^{(1) (3)}	47
Table 28. Bluetooth Qualification Information	48
Table 29. Certification Information	49
Table 30. Certified Antenna List	49
Table 31. Ordering Information	53
Table 32. Revision History	54

List of Figures

Figure 1. Module Naming Convention	6
Figure 2. The Block Diagram of BDE-MP2674R10A.....	12
Figure 3. The Block Diagram of BDE-MP2674R10U and BDE-MP2674R10N.....	13
Figure 4. The Block Diagram of CC2674R10.....	13
Figure 5. Pinout Diagram of BDE-MP2674R10A Top View	21
Figure 6. Pinout Diagram of BDE-MP2674R10U and BDE-MP2674R10N Top View	21
Figure 7. Antenna Placement and Reference Board	33
Figure 8. Radiation Pattern of the Integrated PCB Trace Antenna at 2440MHz	34
Figure 9. Mechanical Drawing of BDE-MP2674R10A.....	35
Figure 10. Mechanical Drawing of BDE-MP2674R10U and BDE-MP2674R10N.....	35
Figure 11. Recommended Module Footprint of BDE-MP2674R10A.....	36
Figure 12. Recommended Module Footprint of BDE-MP2674R10U and BDE-MP2674R10N.....	37
Figure 13. U.FL Connector Drawing and Specification	38
Figure 14. High-Level System Block Diagram	39
Figure 15. Module Placement Recommendations.....	40
Figure 16. Module Marking	42
Figure 17. Carrier Tape Drawing for BDE-MP2674R10 variants	43
Figure 18. 13-INnch Reel Drawing.....	44
Figure 19. Carton Information	44
Figure 20. Reel Label Information.....	45
Figure 21. Carton Label Information	46
Figure 22. Thermal Profile Schematic	47

Reference

[1] CC2674R10 resources: <https://www.ti.com/product/CC2674R10>

1. System Overview

1.1. Block Diagram

BDE-MP2674R10 module series is based on CC2674R10 single chip wireless MCU from Texas Instruments. With clocks, other required passives and antenna/connector (optional) integrated, it allows faster time to market at reduced development cost.

The block diagram of the series modules can be seen in [Figure 2](#) and [Figure 3](#), comprises of:

- 48-MHz HFXT
- 32.768-kHz LFXT
- 32-Mbit SPI flash (SPI flash variants)
- Power inductors and capacitors
- Pull-up resistor
- Passive balun filter
- Decoupling capacitors
- Matching circuit
- PCB trace antenna / U.FL connector for external antenna / ANT pin out for external antenna

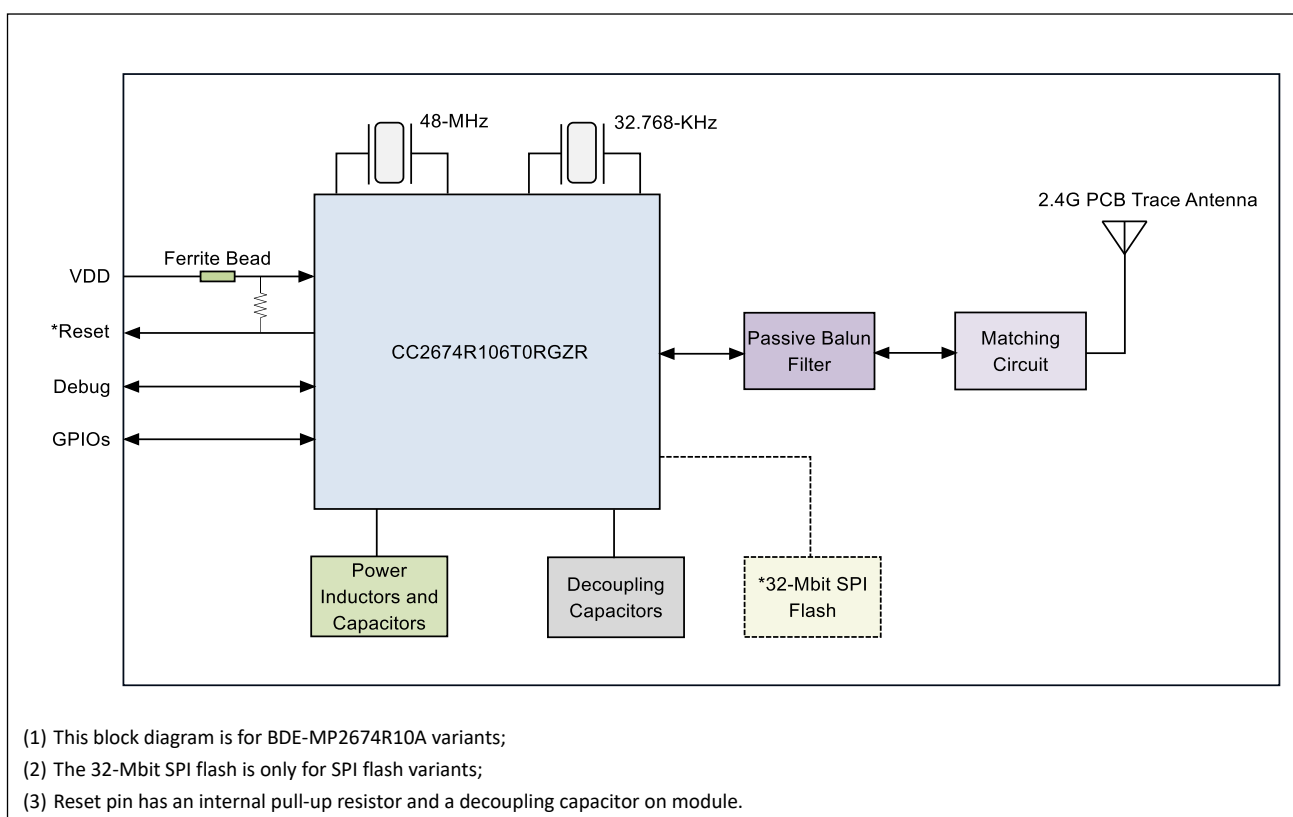
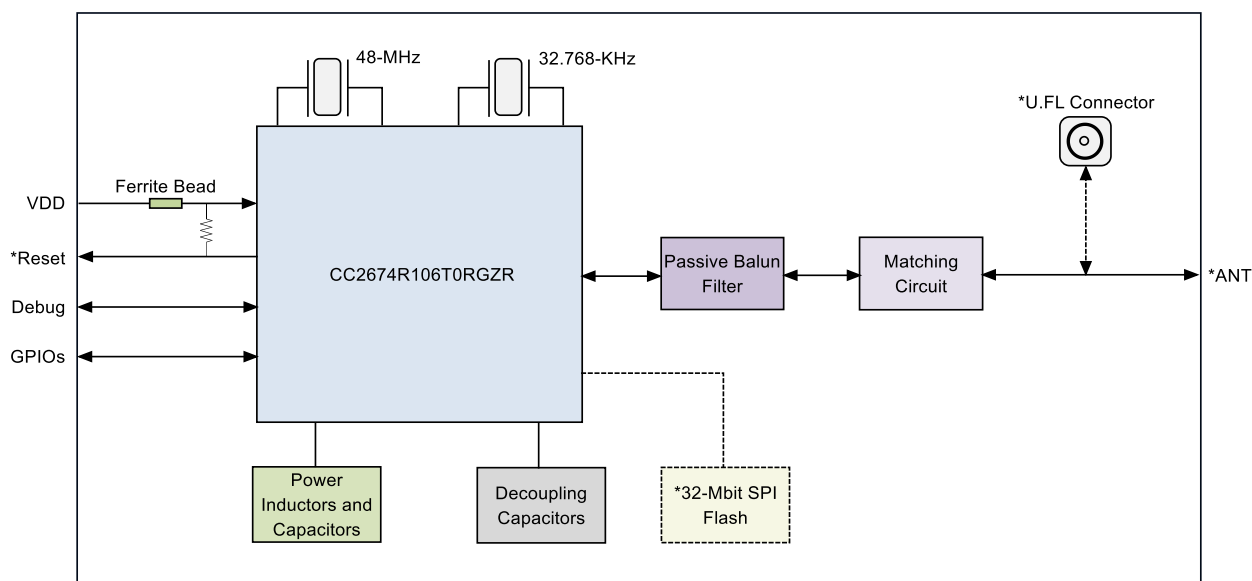


Figure 2. The Block Diagram of BDE-MP2674R10A



- (1) This block diagram is for BDE-MP2674R10U and BDE-MP2674R10N variants;
- (2) The 32-Mbit SPI flash is only for SPI flash variants;
- (3) The U.FL connector is only for BDE-MP2674R10U variants, ANT pin is only for BDE-MP2674R10N variants;
- (4) Reset pin has an internal pull-up resistor and a decoupling capacitor.

Figure 3. The Block Diagram of BDE-MP2674R10U and BDE-MP2674R10N

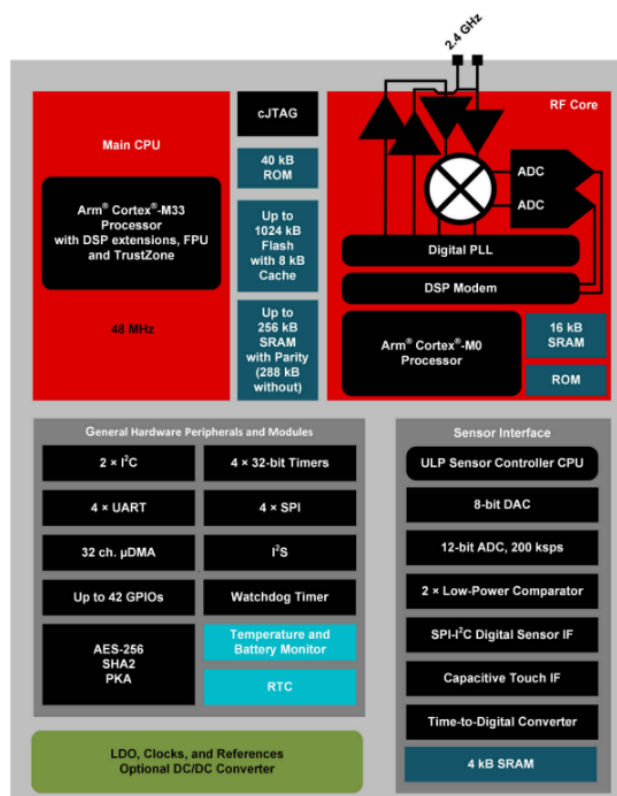


Figure 4. The Block Diagram of CC2674R10

1.2. System CPU

The BDE-MP2674R10 module series utilizes CC2674R10 SimpleLink™ Wireless MCU. The MCU contains an Arm® Cortex®-M33 system CPU with TrustZone®, which runs the application and the higher layers of radio protocol stacks. The system CPU is the foundation of a high-performance, low-cost platform that meets the system requirements of minimal memory implementation, and low-power consumption, while delivering outstanding computational performance and exceptional system response to interrupts.

1.3. Radio (RF Core)

The RF Core is a highly flexible and future proof radio module which contains an Arm Cortex-M0 processor that interfaces the analog RF and base-band circuitry, handles data to and from the system CPU side, and assembles the information bits in a given packet structure. The RF core offers a high level, command-based API to the main CPU that configurations and data are passed through. The Arm Cortex-M0 processor is not programmable by customers and is interfaced through the TI-provided RF driver that is included with the SimpleLink Software Development Kit (SDK).

The RF core can autonomously handle the time-critical aspects of the radio protocols, thus offloading the main CPU, which reduces power and leaves more resources for the user application. Several signals are also available to control external circuitry such as RF switches or range extenders autonomously.

The various physical layer radio formats are partly built as a software defined radio where the radio behavior is either defined by radio ROM contents or by non-ROM radio formats delivered in form of firmware patches with the SimpleLink SDKs. This allows the radio platform to be updated for support of future versions of standards even with over-the-air (OTA) updates while still using the same silicon.

1.3.1. Bluetooth 5.2 Low Energy

The RF Core offers full support for Bluetooth 5.2 Low Energy, including the high-speed 2 Mbps physical layer and the 500 kbps and 125 kbps long range PHYs (Coded PHY) through the TI provided Bluetooth 5.2 stack or through a high-level Bluetooth API. The Bluetooth 5.2 PHY and part of the controller are in radio and system ROM, providing significant savings in memory usage and more space available for applications.

The new high-speed mode allows data transfers up to 2 Mbps, twice the speed of Bluetooth 4.2 and five times the speed of Bluetooth 4.0, without increasing power consumption. In addition to faster speeds, this mode offers significant improvements for energy efficiency and wireless coexistence with reduced radio communication time.

Bluetooth 5.2 also enables unparalleled flexibility for adjustment of speed and range based on application needs, which capitalizes on the high-speed or long-range modes respectively. Data transfers are now possible at 2 Mbps, enabling development of applications using voice, audio, imaging, and data logging that were not previously an option using Bluetooth low energy. With high-speed mode, existing applications deliver faster responses, richer engagement, and longer battery life. Bluetooth 5.2 enables fast, reliable firmware updates.

1.3.2. 802.15.4 Thread, Zigbee, and 6LoWPAN

Through a dedicated IEEE radio API, the RF Core supports the 2.4-GHz IEEE 802.15.4-2011 physical layer (2 Mchips per second Offset-QPSK with DSSS 1:8), used in Thread, Zigbee, and 6LoWPAN protocols. The 802.15.4 PHY and MAC are in radio and system ROM. TI also provides royalty-free protocol stacks for Thread and Zigbee as part of the SimpleLink SDK, enabling a robust end-to-end solution.

1.4. Memory

The up to 1024 KB nonvolatile (Flash) memory provides storage for code and data. The flash memory is in-system programmable and erasable. The last flash memory sector must contain a Customer Configuration section (CCFG) that is used by boot ROM and TI provided drivers to configure the device. This configuration is done through the `ccfg.c` source file that is included in all TI provided examples.

The ultra-low leakage system static RAM (SRAM) is split into up to eight 32 kB blocks and can be used for both storage of data and execution of code. Retention of SRAM contents in Standby power mode is enabled by default and included in Standby mode power consumption numbers. Parity checking for detection of bit errors in memory is built-in, which reduces chip-level soft errors and thereby increases reliability. Parity can be disabled for an additional 32 kB which can be allocated for general purpose SRAM. System SRAM is always initialized to zeroes upon code execution from boot.

To improve code execution speed and lower power when executing code from nonvolatile memory, a 4-way nonassociative 8 kB cache is enabled by default to cache and prefetch instructions read by the system CPU. The cache can be used as a general-purpose RAM by enabling this feature in the Customer Configuration Area (CCFG).

There is a 4 kB ultra-low leakage SRAM available for use with the Sensor Controller Engine which is typically used for storing Sensor Controller programs, data and configuration parameters. This RAM is also accessible by the system CPU. The Sensor Controller RAM is not cleared to zeroes between system resets.

The ROM includes a TI-RTOS kernel and low-level drivers, as well as significant parts of selected radio stacks, which frees up flash memory for the application. The ROM also contains a serial (SPI and UART) bootloader that can be used for initial programming of the device.

The module also provides an option with integrated an on-board 32-Mbit SPI flash for the applications that need to store big application data.

1.5. Sensor Controller

The Sensor Controller contains circuitry that can be selectively enabled in both Standby and Active power modes. The peripherals in this domain can be controlled by the Sensor Controller Engine, which is a proprietary power-optimized CPU. This CPU can read and monitor sensors or perform other tasks autonomously; thereby significantly reducing power consumption and offloading the system CPU.

The Sensor Controller Engine is user programmable with a simple programming language that has syntax similar to C. This programmability allows for sensor polling and other tasks to be specified as sequential algorithms rather than static

configuration of complex peripheral modules, timers, DMA, register programmable state machines, or event routing.

The peripherals in the Sensor Controller include the following:

- The low-power clocked comparator can be used to wake the system CPU from any state in which the comparator is active. A configurable internal reference DAC can be used in conjunction with the comparator. The output of the comparator can also be used to trigger an interrupt or the ADC.
- Capacitive sensing functionality is implemented through the use of a constant current source, a time-to-digital converter, and a comparator. The continuous time comparator in this block can also be used as a higher accuracy alternative to the low-power clocked comparator. The Sensor Controller takes care of baseline tracking, hysteresis, filtering, and other related functions when these modules are used for capacitive sensing.
- The ADC is a 12-bit 200 kps ADC with eight inputs and a built-in voltage reference. The ADC can be triggered by many different sources including timers, I/O pins, software, and comparators.
- The analog modules can connect to up to eight different GPIOs.
- Dedicated SPI master with up to 6 MHz clock speed.

The peripherals in the Sensor Controller can also be controlled from the main application processor.

1.6. Cryptography

The device comes with a wide set of modern cryptography-related hardware accelerator, drastically reducing code footprint and execution time for cryptographic operations. It also has the benefit of being lower power and improves availability and responsiveness of the system because the cryptography operations run in a background hardware thread.

Together with a large selection of open-source cryptography libraries provided with the Software Development Kit (SDK), this allows for secure and future proof IoT applications to be easily built on top of the platform. The hardware accelerator modules are:

- True Random Number Generator (TRNG) module provides a true, nondeterministic noise source for the purpose of generating keys, initialization vectors (IVs), and other random number requirements. The TRNG is built on 24 ring oscillators that create unpredictable output to feed a complex nonlinear-combinatorial circuit.
- Secure Hash Algorithm 2 (SHA-2) with support for SHA224, SHA256, SHA384, and SHA512.
- Advanced Encryption Standard (AES) with 128, 192 and 256 bit key lengths.
- Public Key Accelerator - Hardware accelerator supporting mathematical operations needed for elliptic curves up to 512 bits.

Through use of these modules and the TI provided cryptography drivers, the following capabilities are available for application or stack:

- Key Agreement Schemes
- Signature Processing
- Curve Support
- Message Authentication Codes
- Block cipher mode of operation
- Hash Algorithm
- True random number generation

Other capabilities, such as RSA encryption and signatures (using keys as large as 2048 bits) as well as other ECC curves

such as Curve1174, can be implemented using the provided public key accelerator but are not part of the TI SimpleLink SDK for the CC2674R10 device.

1.7. Timer

A large selection of timers is available as part of the device. These timers are:

- Real-Time Clock (RTC)
- General Purpose Timers (GPTIMER)
- Sensor Controller Timers
- Radio Timer
- Watchdog timer
- Always On Watchdog timer (AON_WDT)

1.8. Serial Peripherals and I/O

The SPI interface provides a standardized synchronous serial interface to communicate with devices compatible with SPI (3 and 4 wire), MICROWIRE and TI Synchronous Serial Format. The SPIs support master/slave operation up to 12 MHz, programmable clock bit rate with prescaler, as well as configurable phase and polarity.

The UART interface implements universal asynchronous receiver and transmitter functions. The UART supports flexible baud-rate generation up to a maximum of 3 Mbps with FIFO, multiple data sizes, stop and parity bits as well as hardware handshake.

The I2S interface provides a standardized interface to exchange digital audio with devices compatible with this standard, including ADCs, DACs and CODECs. The I2S can also receive pulse-density modulation (PDM) data from devices such as digital microphones and perform conversion to PCM data.

The I2C interface enables low speed serial communications with devices compatible with the I2C standard. The I2C interface can handle both standard (100 kHz) and fast (400 kHz) speeds, as well as four modes of operation: master transmit/receive and slave transmit/receive.

The I/O controller (IOC) controls the digital I/O pins and contains multiplexer circuitry to allow a set of peripherals to be assigned to I/O pins in a flexible manner. All digital I/Os are interrupt and wake-up capable, have a programmable pullup and pulldown function, and can generate an interrupt on a negative or positive edge (configurable). When configured as an output, pins can function as either push-pull or open-drain. Five GPIOs have high-drive capabilities, which are marked in bold in Section [2.1](#). All digital peripherals can be connected to any digital pin on the device.

1.9. Battery and Temperature Monitor

A combined temperature and battery voltage monitor is available in the device. The battery and temperature monitor allows an application to continuously monitor on-chip temperature and supply voltage and respond to changes in environmental conditions as needed. The module contains window comparators to interrupt the system CPU when temperature or supply voltage go outside defined windows. These events can also be used to wake up the device from Standby mode through the Always-On (AON) event fabric.

1.10. μ DMA

The device includes a direct memory access (μ DMA) controller. The μ DMA controller provides a way to offload data-transfer tasks from the system CPU, thus allowing for more efficient use of the processor and the available bus bandwidth. The μ DMA controller can perform a transfer between memory and peripherals. The μ DMA controller has dedicated channels for each supported on-chip module and can be programmed to automatically perform transfers between peripherals and memory when the peripheral is ready to transfer more data.

1.11. Debug

The debug subsystem implements two IEEE standards for debug and test purposes:

IEEE 1149.7 Class 4: Reduced-pin and Enhanced-functionality Test Access Port and Boundary-scan Architecture. This is known by the acronym cJTAG (compact JTAG) and this device uses only two pins to communicate to the target: TMS (JTAG_TMSC) and TCK (JTAG_TCKC). This is the default mode of operation.

IEEE standard 1149.1: Test Access Port and Boundary Scan Architecture Test Access Port (TAP). This standard is known by the acronym JTAG and this device uses four pins to communicate to the target: TMS (JTAG_TMSC), TCK (JTAG_TCKC), TDI (JTAG_TDI) and TDO (JTAG_TDO).

The debug subsystem also implements a user-configurable firewall to control unauthorized access to debug/test ports.

1.12. Clock

The module has the following internal system clocks.

SCLK_MF is an internal 2 MHz clock that is used by the Sensor Controller in low-power mode and also for internal power management circuitry. The SCLK_MF clock is always driven by the internal 2 MHz RC Oscillator (RCOSC_MF).

SCLK_LF is the 32.768 kHz internal low-frequency system clock. It can be used by the Sensor Controller for ultra-low-power operation and is also used for the RTC and to synchronize the radio timer before or after Standby power mode. SCLK_LF can be driven by the internal 32.8 kHz RC Oscillator (RCOSC_LF), a 32.768 kHz watch-type crystal, or a clock input on any digital IO.

When using a crystal or the internal RC oscillator, the device can output the 32 kHz SCLK_LF signal to other devices, thereby reducing the overall system cost.

The module includes two crystals on board, a high frequency crystal (HFXT) with 48-MHz and a low frequency crystal (LFXT) with 32.768-KHz.

1.13. Network Processor

Depending on the product configuration, the module device can function as a wireless network processor (WNP - a device running the wireless protocol stack with the application running on a separate host MCU), or as a system-on-chip (SoC)

with the application and protocol stack running on the system CPU inside the device. In the first case, the external host MCU communicates with the device using SPI or UART. In the second case, the application must be written according to the application framework supplied with the wireless protocol stack.

1.14. Power Management

To minimize power consumption, the CC2674R10 supports a number of power modes and power management features.

Table 3. Power Mode

Mode	Software Configurable Power Modes				Reset Pin Held
	Active	Idle	Standby	Shutdown	
CPU	Active	Off	Off	Off	Off
Flash	On	Available	Off	Off	Off
SRAM	On	On	Retention	Off	Off
Supply System	On	On	Duty Cycled	Off	Off
Register and CPU retention	Full	Full	Partial	No	No
SRAM retention	Full	Full	Full	Off	Off
48 MHz high-speed clock (SCLK_HF)	XOSC_HF or RCOSC_HF	XOSC_HF or RCOSC_HF	Off	Off	Off
2 MHz medium-speed clock (SCLK_MF)	RCOSC_MF	RCOSC_MF	Available	Off	Off
32 kHz low-speed clock (SCLK_LF)	XOSC_LF or RCOSC_LF	XOSC_LF or RCOSC_LF	XOSC_LF or RCOSC_LF	Off	Off
Peripherals	Available	Available	Off	Off	Off
Sensor Controller	Available	Available	Available	Off	Off
Wake-up on RTC	Available	Available	Available	Off	Off
Wake-up on pin edge	Available	Available	Available	Available	Off
Wake-up on reset pin	On	On	On	On	On
Brownout detector (BOD)	On	On	Duty Cycled	Off	Off
Power-on reset (POR)	On	On	On	Off	Off
Watchdog timer (WDT)	Available	Available	Paused	Off	Off
Always-on Watchdog timer (AON_WDT)	Available	Available	Available	Off	Off

In the Active mode, the application system CPU is actively executing code. Active mode provides normal operation of the processor and all of the peripherals that are currently enabled. The system clock can be any available clock source.

In Idle mode, all active peripherals can be clocked, but the Application CPU core and memory are not clocked and no code is executed. Any interrupt event brings the processor back into active mode.

In Standby mode, only the always-on (AON) domain is active. An external wake-up event, RTC event, or Sensor Controller event is required to bring the device back to active mode. MCU peripherals with retention do not need to be reconfigured when waking up again, and the CPU continues execution from where it went into standby mode. All GPIOs are latched in standby mode.

In Shutdown mode, the device is entirely turned off (including the AON domain and Sensor Controller), and the I/Os are latched with the value they had before entering shutdown mode. A change of state on any I/O pin defined as a wake from shutdown pin wakes up the device and functions as a reset trigger. The CPU can differentiate between reset in this way and reset-by-reset pin or power-on reset by reading the reset status register. The only state retained in this mode is the latched I/O state and the flash memory contents.

The Sensor Controller is an autonomous processor that control the peripherals in the Sensor Controller independently of the system CPU. This means that the system CPU does not have to wake up, for example to perform an ADC sampling or poll a digital sensor over SPI, thus saving both current and wake-up time that would otherwise be wasted. The Sensor Controller Studio tool enables the user to program the Sensor Controller, control its peripherals, and wake up the system CPU as needed. All Sensor Controller peripherals can also be controlled by the system CPU.

The power, RF and clock management for the CC2674R10 device require specific configuration and handling by software for optimized performance. This configuration and handling are implemented in the TI-provided drivers that are part of the CC2674R10 software development kit (SDK). Therefore, BDE highly recommends using this software framework for all application development on the device. The complete SDK with TI-RTOS (optional), device drivers, and examples are offered free of charge in source code.

1.15. Antenna

The module series provides three different types of antenna integration options integrated PCB trace antenna, U.FL connector and ANT pin for connecting external antenna. Detail characteristics for the antennas can be found in [Section 3.3](#).

2. Pinout Functions

The module series is with LCC-36 package for BDE-MP2674R10A variants and LCC-39 package for BDE-MP2674R10U and BDE-MP2674R10N variants, 36 or 39 pads are exposed for user. This section describes pinout functions of the module in details.

2.1. Pinout Diagram

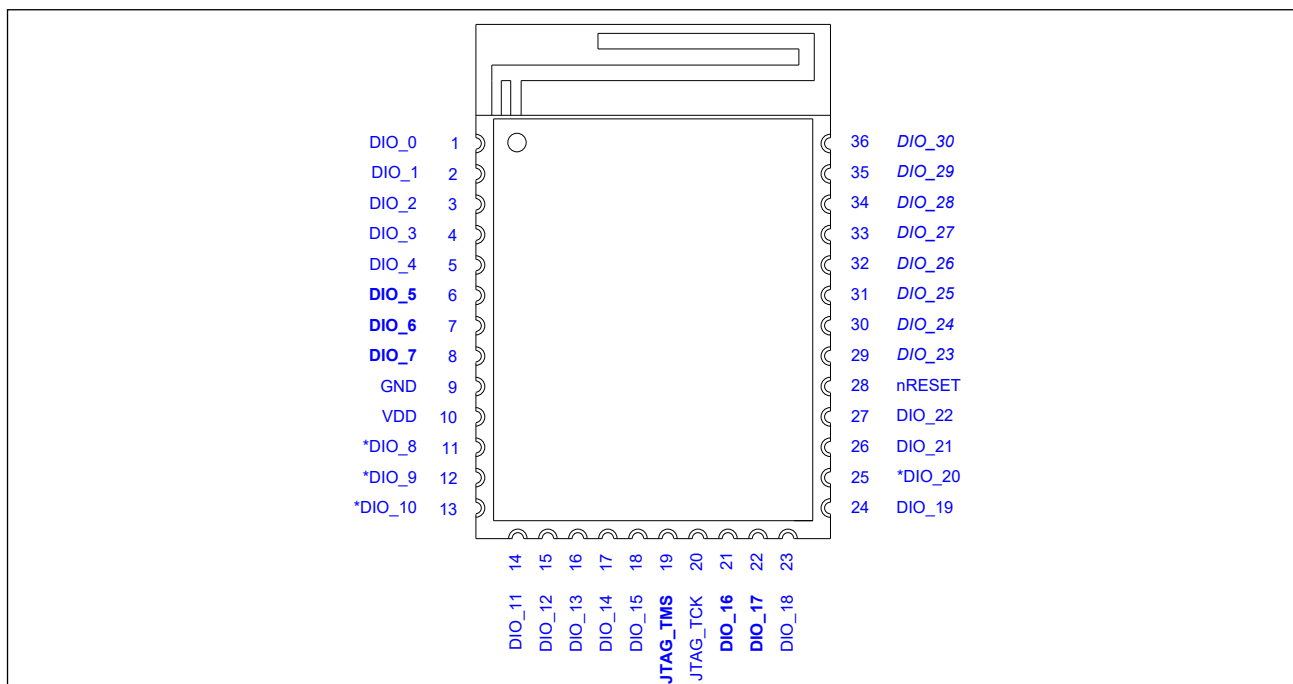


Figure 5. Pinout Diagram of BDE-MP2674R10A Top View

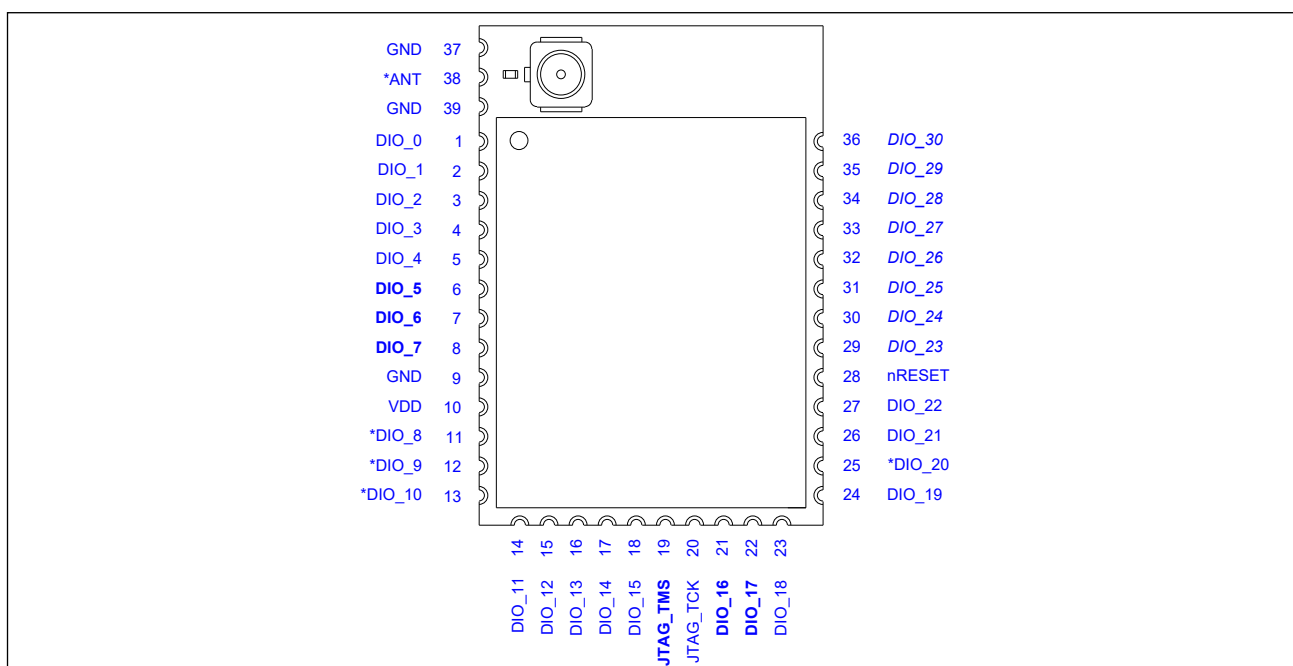


Figure 6. Pinout Diagram of BDE-MP2674R10U and BDE-MP2674R10N Top View

The following I/O pins marked in [Figure 5](#) and [Figure 6](#) in **bold** have high-drive capabilities:

- Pin 6, DIO5
- Pin 7, DIO6
- Pin 8, DIO7
- Pin 19, JTAG_TMS
- Pin 21, DIO16
- Pin 22, DIO17

The following I/O pins marked in [Figure 5](#) and [Figure 6](#) in *italics* have analog capabilities:

- Pin 29, DIO23
- Pin 30, DIO24
- Pin 31, DIO25
- Pin 32, DIO26
- Pin 33, DIO27
- Pin 34, DIO28
- Pin 35, DIO29
- Pin 36, DIO30

The following four I/O pins are assigned to on-board 32-Mbit SPI flash for SPI flash variants:

- Pin 11, SFL_MISO_DIO8
- Pin 12, SFL_MOSI_DIO9
- Pin 13, SFL_CLK_DIO10
- Pin 25, SFL_CS_DIO20

Pin 38 is for connecting external antenna for BDE-MP2674R10N variants, if U.FL variants are used, leave this pin NC.

2.2. Pinout Descriptions

[Table 4](#) describes the definitions of the pins of the module. Pin number of CC2674R10 chip is also stated here, because the chip pin is referred to in the software design kit (SDK).

Table 4. Pin Description⁽¹⁾

Module Pin #	Pin Name	Type	CC2674R106T0RGZR Pin #	Description
1	DIO_0	I/O	5	GPIO
2	DIO_1	I/O	6	GPIO
3	DIO_2	I/O	7	GPIO
4	DIO_3	I/O	8	GPIO
5	DIO_4	I/O	9	GPIO
6	DIO_5	I/O	10	GPIO, high-drive capability
7	DIO_6	I/O	11	GPIO, high-drive capability
8	DIO_7	I/O	12	GPIO, high-drive capability
9	GND	Ground	-	Power ground
10	VDD	Power	-	Power supply
11	DIO_8	I/O	14	SFL_MISO ⁽²⁾ , GPIO
12	DIO_9	I/O	15	SFL_MOSI ⁽²⁾ , GPIO
13	DIO_10	I/O	16	SFL_SCLK ⁽²⁾ , GPIO

Module Pin #	Pin Name	Type	CC2674R106T0RGZR Pin #	Description
14	DIO_11	I/O	17	GPIO
15	DIO_12	I/O	18	GPIO
16	DIO_13	I/O	19	GPIO
17	DIO_14	I/O	20	GPIO
18	DIO_15	I/O	21	GPIO
19	JTAG_TMS	I/O	24	JTAG TMS, high-drive capability
20	JTAG_TCK	I	25	JTAG TCK
21	DIO_16	I/O	26	GPIO, JTAG_TDO, high-drive capability
22	DIO_17	I/O	27	GPIO, JTAG_TDI, high-drive capability
23	DIO_18	I/O	28	GPIO
24	DIO_19	I/O	29	GPIO
25	DIO_20	I/O	30	SFL_CS ⁽²⁾ , GPIO
26	DIO_21	I/O	31	GPIO
27	DIO_22	I/O	32	GPIO
28	nRESET	I	35	Reset, active-low, 100K ohm internal pull-up resistor
29	DIO_23	I/O	36	GPIO, analog capability
30	DIO_24	I/O	37	GPIO, analog capability
31	DIO_25	I/O	38	GPIO, analog capability
32	DIO_26	I/O	39	GPIO, analog capability
33	DIO_27	I/O	40	GPIO, analog capability
34	DIO_28	I/O	41	GPIO, analog capability
35	DIO_29	I/O	42	GPIO, analog capability
36	DIO_30	I/O	43	GPIO, analog capability
37 ⁽³⁾	GND	Ground	-	Power ground
38 ⁽³⁾	ANT	RF	-	Antenna port
39 ⁽³⁾	GND	Ground	-	Power ground

(1) For pin multiplexing details, refer to [CC2674R10 SimpleLink™ Arm® Cortex®-M33 multiprotocol 2.4-GHz wireless MCU with 1-MB flash](#);

(2) These four pins are used as SPI for on-board 32-Mbit flash in SPI flash module variants. They can be used as GPIOs in none SPI flash module variants;

(3) Pin 37, Pin 38 and Pin 39 are only included in BDE-MP2674R10U and BDE-MP2674R10N variants.

2.3. Connections for Unused Pins

Table 5. Connections for Unused Pins

Function	Signal Name	Acceptable Practice	Proffered Practice
GPIO (Digital or analog)	DIO _n	NC or GND	NC

3. Specifications

3.1. Electrical Characteristics

3.1.1. Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Over operating free-air temperature range (unless otherwise noted).

Table 6. Absolute Maximum Ratings

Parameter	MIN	MAX	Unit	Note
VDD, Supply voltage	-0.3	4.1	V	
Voltage on any digital pins	-0.3	VDD+0.3≤4.1	V	Including DIOs with analog capability
Voltage on ADC input	-0.3	VDD	V	Voltage scaling enabled
	-0.3	1.49	V	Voltage scaling disabled, internal reference
	-0.3	VDD/2.9	V	Voltage scaling disabled, VDD as reference
Input level, for ANT pin (Pin38)		5	dBm	For –N variants
TSTG, Storage temperature	-40	125	°C	

3.1.2. ESD Ratings

Table 7. ESD Ratings

Parameter	Description	Value	Unit	Note
Electrostatic discharge	Contact discharge	4000	V	As per EN 301-489
	Air discharge	8000	V	As per EN 301-489

3.1.3. Recommended Operating Conditions

Operation at or near maximum operating temperature for extended durations will result in a reduction in lifetime.

Over operating free-air temperature range (unless otherwise noted).

Table 8. Recommended Operating Conditions

Parameter	MIN	TYP	MAX	Unit	Note
VDD, Supply voltage	1.8	3.3	3.8	V	
	2.3	3.3	3.8	V	For SPI flash variants
TA, Operating Temperature	-40	25	85	°C	
	-40	25	105	°C	For -IN variants
Rising supply voltage slew rate	0		100	mV/μs	
Falling supply voltage slew rate	0		20	mV/μs	

3.1.4. Power Consumption

The measurement is made with $T_A = 25\text{ °C}$, VDD = 3.0 V, DCDC enabled, GLDO disabled, none SPI flash variants unless otherwise noted.

Table 9. Power Consumption – Power Modes

Parameter	Test Condition	TYP	Unit
Core Current Consumption			
Reset	Reset. RESET pin asserted or VDD below power-on-reset threshold	150	nA
Shutdown	Shutdown. No clocks running, no retention	128.6	nA
Standby without cache retention	RTC running, CPU, 256 kB RAM and (partial) register retention. RCOSC_LF	1.06	uA
	RTC running, CPU, 128 kB RAM and (partial) register retention. RCOSC_LF	0.96	uA
	RTC running, CPU, 256 kB RAM and (partial) register retention. XOSC_LF	1.19	uA
	RTC running, CPU, 128 kB RAM and (partial) register retention. XOSC_LF	1.09	uA
Standby with cache retention	RTC running, CPU, 256 kB RAM and (partial) register retention. RCOSC_LF	2.55	uA
	RTC running, CPU, 128 kB RAM and (partial) register retention. RCOSC_LF	2.45	uA
	RTC running, CPU, 256 kB RAM and (partial) register retention. XOSC_LF	2.66	uA
	RTC running, CPU, 128 kB RAM and (partial) register retention. XOSC_LF	2.57	uA
Idle	Supply Systems and RAM powered RCOSC_HF	720.9	uA
Active	MCU running CoreMark at 48 MHz with parity enabled RCOSC_HF	4.13	mA
	MCU running CoreMark at 48 MHz with parity disabled RCOSC_HF	3.97	mA
Peripheral Current Consumption			
Peripheral, power domain	Delta current with domain enabled	74.0	uA
Peripheral, Serial power domain	Delta current with domain enabled	6.89	uA
Peripheral, RF Core	Delta current with power domain enabled, clock enabled, RF core idle	120.4	uA
Peripheral, μDMA	Delta current with clock enabled, module is idle	68.2	uA
Peripheral, Timers	Delta current with clock enabled, module is idle	115.4	uA
Peripheral, I2C	Delta current with clock enabled, module is idle	11.5	uA
Peripheral, I2S	Delta current with clock enabled, module is idle	26.1	uA
Peripheral, SPI	Delta current with clock enabled, module is idle	65.9	uA
Peripheral, UART	Delta current with clock enabled, module is idle	135.1	uA
Peripheral, CRYPTO (AES)	Delta current with clock enabled, module is idle	18.6	uA
Peripheral, PKA	Delta current with clock enabled, module is idle	79.3	uA
Peripheral, TRNG	Delta current with clock enabled, module is idle	24.69	uA

Parameter	Test Condition	TYP	Unit
Sensor Controller Engine Consumption			
Active mode	24 MHz, infinite loop	808.5	uA
Low-power mode	2 MHz, infinite loop	30.1	uA

Table 10. Power Consumption – Radio Modes

Power Mode	Test Condition	TYP	Unit
Radio receive current	2440 MHz, Bluetooth Low Energy	6.4	mA
Radio transmit current	0 dBm output power setting 2440 MHz, Bluetooth Low Energy	7.3	mA
	+5 dBm output power setting 2440 MHz, Bluetooth Low Energy	9.8	mA

3.1.5. Clock Characteristics

Table 11. 48-MHz Crystal Oscillator (XOSC_HF) Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Crystal frequency			48		MHz
ESR, Equivalent series resistance				40	Ω
Frequency tolerance	TA: 25°C	-10		10	ppm
Frequency stability	TA: -40°C ~ 85°C or -40°C ~ 105°C	-20		20	ppm
CL, Crystal load capacitance			7		pF

Table 12. 32.768-KHz Crystal Oscillator (XOSC_LF) Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Crystal frequency			32.768		KHz
ESR, Equivalent series resistance				70	k Ω
Frequency tolerance	TA: 25°C	-20		20	ppm
CL, Crystal load capacitance			12.5		pF

3.1.6. Reset Timing

Table 13. Reset Timing

Parameter	MIN	TYP	MAX	Unit
nRESET low duration	1			us

3.1.7. UART Characteristics

Table 14. UART Characteristics

Parameter	MIN	TYP	MAX	Unit
UART baud rate			3	MBaud

3.1.8. SPI Characteristics

Table 15. SPI Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
SPI clock frequency	Primary Mode $1.71 < VDD < 3.8$			12	MHz
	Secondary Mode $2.7 < VDD < 3.8$			8	
	Secondary Mode $VDD < 2.7$			7	
SPI duty cycle		45	50	55	%

3.1.9. GPIO DC Characteristics

Table 16. GPIO DC Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
TA = 25 °C, VDD = 1.8 V					
GPIO VOH at 8 mA load	IOCURR = 2, high-drive GPIOs only		1.56		
GPIO VOL at 8 mA load	IOCURR = 2, high-drive GPIOs only		0.24		V
GPIO VOH at 4 mA load	IOCURR = 1		1.59		V
GPIO VOL at 4 mA load	IOCURR = 1		0.21		V
GPIO pullup current	Input mode, pullup enabled, Vpad = 0 V		73		μA
GPIO pulldown current	Input mode, pulldown enabled, Vpad = VDD		19		μA
GPIO low-to-high input transition, with hysteresis	IH = 1, transition voltage for input read as 0 → 1		1.08		V
GPIO high-to-low input transition, with hysteresis	IH = 1, transition voltage for input read as 1 → 0		0.73		V
GPIO input hysteresis	IH = 1, difference between 0 → 1 and 1 → 0 points		0.35		V
TA = 25 °C, VDD = 3.0 V					
GPIO VOH at 8 mA load	IOCURR = 2, high-drive GPIOs only		2.59		V
GPIO VOL at 8 mA load	IOCURR = 2, high-drive GPIOs only		0.42		V
GPIO VOH at 4 mA load	IOCURR = 1		2.63		V
GPIO VOL at 4 mA load	IOCURR = 1		0.40		V
TA = 25 °C, VDD = 3.8 V					
GPIO pullup current	Input mode, pullup enabled, Vpad = 0 V		282		μA
GPIO pulldown current	Input mode, pulldown enabled, Vpad = VDD		110		μA
GPIO low-to-high input transition, with hysteresis	IH = 1, transition voltage for input read as 0 → 1		1.97		V
GPIO high-to-low input transition, with hysteresis	IH = 1, transition voltage for input read as 1 → 0		1.55		V
GPIO input hysteresis	IH = 1, difference between 0 → 1 and 1 → 0 points		0.42		V
TA = 25 °C					
VIH	Lowest GPIO input voltage reliably interpreted as a High	0.8*VDD			V
VIL	Highest GPIO input voltage reliably interpreted as a Low			0.2*VDD	V

3.1.10. ADC Characteristics

Table 17. ADC Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Resolution			12		bit
Input voltage range		0		VDD	V
Reference voltage	Equivalent fixed internal reference (input voltage scaling enabled). For best accuracy, the ADC conversion should be initiated through the TI-RTOS API in order to include the gain/offset compensation factors stored in FCFG1		4.3		V
Reference voltage	Fixed internal reference (input voltage scaling disabled). For best accuracy, the ADC conversion should be initiated through the TI-RTOS API in order to include the gain/offset compensation factors stored in FCFG1. This value is derived from the scaled value (4.3 V) as follows: $V_{ref} = 4.3 \text{ V} \times 1408 / 4095$		1.48		V
Reference voltage	VDD as reference, input voltage scaling enabled		VDD		V
	VDD as reference, input voltage scaling disabled		VDD/2.82		V
Sampling rate				200	ksps

For more details on the ADC characteristic, please refer to CC2674R10 datasheet: [CC2674R10 SimpleLink™ Arm® Cortex®-M33 multiprotocol 2.4-GHz wireless MCU with 1-MB flash](#).

3.1.11. DAC Characteristics

Table 18. DAC Characteristics

Parameter	Test Condition	MIN	TYP	MAX	Unit
Resolution			8		bit
Supply voltage	Any load, any VREF, pre-charge OFF, DAC charge-pump ON	1.8		3.8	V
	External Load, any VREF, pre-charge OFF, DAC charge-pump OFF	2.0		3.8	V
	Any load, VREF = DCOUPL, pre-charge ON	2.6		3.8	V
Clock frequency	Buffer ON (recommended for external load)	16		250	kHz
	Buffer OFF (internal load)	16		1000	kHz

For more details on the DAC characteristic, please refer to CC2674R10 datasheet: [CC2674R10 SimpleLink™ Arm® Cortex®-M33 multiprotocol 2.4-GHz wireless MCU with 1-MB flash](#).

3.1.12. Comparator Characteristics

Tc = 25 °C, VDD = 3.0 V, unless otherwise noted.

Table 19. Low-Power Clocked Comparator

Parameter	Test Condition	MIN	TYP	MAX	Unit
Input voltage range		0		VDD	V
Clock frequency			32		KHz
Internal reference voltage	Using internal DAC with VDD as reference voltage, DAC code = 0 - 255	0.024		2.865	V
Offset	Measured at VDD / 2, includes error from internal DAC		±5		mV
Decision time	Step from -50 mV to 50 mV		1		Clock Cycle

Table 20. Continuous Time Comparator

Parameter	Test Condition	MIN	TYP	MAX	Unit
Input voltage range		0		VDD	V
Offset	Measured at VDD / 2, includes error from internal DAC		±5		mV
Decision time	Step from -50 mV to 50 mV		0.78		μs
Current consumption	Internal reference		8.6		μA

3.2. RF Characteristics

The measurement is made with the evaluation board for BDE-MP2674R10 with TA = 25 °C, VDD = 3.3 V, DCDC enabled, GLDO disabled, unless otherwise noted.

3.2.1. BLE Performance: Receiver Characteristics

Table 21. Receive (RX) Characteristics – Bluetooth

Parameter	Test Condition	TYP	Unit
BLE 125Kbps (LE Coded) Receiver Characteristics			
Receiver sensitivity	BER = 10 ⁻³	-103	dBm
Receiver saturation	BER = 10 ⁻³	> 5	dBm
Co-channel rejection	Wanted signal at -67 dBm, modulated interferer in channel, BER = 10 ⁻³	-1.5	dB
Selectivity, ±1 MHz	Wanted signal at -67 dBm, modulated interferer at ±1 MHz, BER = 10 ⁻³	8 / 4.5	dB
Selectivity, ±2 MHz	Wanted signal at -67 dBm, modulated interferer at ±2 MHz, BER = 10 ⁻³	44 / 39	dB
Selectivity, ±3 MHz	Wanted signal at -67 dBm, modulated interferer at ±3 MHz, BER = 10 ⁻³	43 / 43	dB
Selectivity, ±4 MHz	Wanted signal at -67 dBm, modulated interferer at ±4 MHz, BER = 10 ⁻³	44 / 43	dB
Selectivity, ±6 MHz	Wanted signal at -79 dBm, modulated interferer at ±6 MHz, BER = 10 ⁻³	48 / 43	dB
Selectivity, ±7 MHz	Wanted signal at -79 dBm, modulated interferer at ±7 MHz, BER = 10 ⁻³	51 / 45	dB
Selectivity, image frequency	Wanted signal at -67 dBm, modulated interferer at image frequency, BER = 10 ⁻³	39	dB
Selectivity, image frequency ±1	Note that Image frequency + 1 MHz is the Co- channel -1 MHz. Wanted	4.5 / 44	dB

Parameter	Test Condition	TYP	Unit
MHz	signal at -79 dBm, modulated interferer at ± 1 MHz from image frequency, BER = 10^{-3}		
BLE 500Kbps (LE Coded) Receiver Characteristics			
Receiver sensitivity	BER = 10^{-3}	-98	dBm
Receiver saturation	BER = 10^{-3}	> 5	dBm
Co-channel rejection	Wanted signal at -67 dBm, modulated interferer in channel, BER = 10^{-3}	-3.5	dB
Selectivity, ± 1 MHz	Wanted signal at -67 dBm, modulated interferer at ± 1 MHz, BER = 10^{-3}	8 / 4	dB
Selectivity, ± 2 MHz	Wanted signal at -67 dBm, modulated interferer at ± 2 MHz, BER = 10^{-3}	41 / 37	dB
Selectivity, ± 3 MHz	Wanted signal at -67 dBm, modulated interferer at ± 3 MHz, BER = 10^{-3}	44 / 41	dB
Selectivity, ± 4 MHz	Wanted signal at -67 dBm, modulated interferer at ± 4 MHz, BER = 10^{-3}	44 / 43	dB
Selectivity, ± 6 MHz	Wanted signal at -79 dBm, modulated interferer at ± 6 MHz, BER = 10^{-3}	46 / 43	dB
Selectivity, ± 7 MHz	Wanted signal at -79 dBm, modulated interferer at ± 7 MHz, BER = 10^{-3}	49 / 45	dB
Selectivity, image frequency	Wanted signal at -67 dBm, modulated interferer at image frequency, BER = 10^{-3}	37	dB
Selectivity, image frequency ± 1 MHz	Note that Image frequency + 1 MHz is the Co- channel -1 MHz. Wanted signal at -72 dBm, modulated interferer at ± 1 MHz from image frequency, BER = 10^{-3}	4 / 46	dB
BLE 1Mbps (LE 1M) Receiver Characteristics			
Receiver sensitivity	BER = 10^{-3}	-95	dBm
Receiver saturation	BER = 10^{-3}	> 5	dBm
Co-channel rejection	Wanted signal at -67 dBm, modulated interferer in channel, BER = 10^{-3}	-6	dB
Selectivity, ± 1 MHz	Wanted signal at -67 dBm, modulated interferer at ± 1 MHz, BER = 10^{-3}	7 / 4	dB
Selectivity, ± 2 MHz	Wanted signal at -67 dBm, modulated interferer at ± 2 MHz, BER = 10^{-3}	40 / 33	dB
Selectivity, ± 3 MHz	Wanted signal at -67 dBm, modulated interferer at ± 3 MHz, BER = 10^{-3}	36 / 41	dB
Selectivity, ± 4 MHz	Wanted signal at -67 dBm, modulated interferer at ± 4 MHz, BER = 10^{-3}	36 / 45	dB
Selectivity, ± 5 MHz or more	Wanted signal at -67 dBm, modulated interferer at ± 5 MHz, BER = 10^{-3}	40	dB
Selectivity, image frequency	Wanted signal at -67 dBm, modulated interferer at image frequency, BER = 10^{-3}	33	dB
Selectivity, image frequency ± 1 MHz	Note that Image frequency + 1 MHz is the Co- channel -1 MHz. Wanted signal at -67 dBm, modulated interferer at ± 1 MHz from image frequency, BER = 10^{-3}	4 / 41	dB
Out-of-band blocking	30 MHz to 2000 MHz	-10	dBm
Out-of-band blocking	2003 MHz to 2399 MHz	-18	dBm
Out-of-band blocking	2484 MHz to 2997 MHz	-12	dBm
Out-of-band blocking	3000 MHz to 12.75 GHz (excluding VCO frequency)	-2	dBm
Intermodulation	Wanted signal at 2402 MHz, -64 dBm. Two interferers at 2405 and 2408 MHz respectively, at the given power level	-42	dBm
BLE 2Mbps (LE 2M) Receiver Characteristics			
Receiver sensitivity	BER = 10^{-3}	-90	dBm
Receiver saturation	BER = 10^{-3}	> 5	dBm
Co-channel rejection	Wanted signal at -67 dBm, modulated interferer in channel, BER = 10^{-3}	-7	dB
Selectivity, ± 2 MHz	Wanted signal at -67 dBm, modulated interferer at ± 2 MHz, BER = 10^{-3}	8 / 4	dB
Selectivity, ± 4 MHz	Wanted signal at -67 dBm, modulated interferer at ± 4 MHz, BER = 10^{-3}	35 / 32	dB

Parameter	Test Condition	TYP	Unit
Selectivity, ± 6 MHz	Wanted signal at -67 dBm, modulated interferer at ± 6 MHz, BER = 10^{-3}	37 / 34	dB
Selectivity, image frequency	Wanted signal at -67 dBm, modulated interferer at image frequency, BER = 10^{-3}	4	dB
Selectivity, image frequency ± 2 MHz	Note that Image frequency + 1 MHz is the Co- channel -1 MHz. Wanted signal at -67 dBm, modulated interferer at ± 1 MHz from image frequency, BER = 10^{-3}	-7 / 36	dB
Out-of-band blocking	30 MHz to 2000 MHz	-16	dBm
Out-of-band blocking	2003 MHz to 2399 MHz	-21	dBm
Out-of-band blocking	2484 MHz to 2997 MHz	-15	dBm
Out-of-band blocking	3000 MHz to 12.75 GHz (excluding VCO frequency)	-20	dBm
Intermodulation	Wanted signal at 2402 MHz, -64 dBm. Two interferers at 2405 and 2408 MHz respectively, at the given power level	-37	dBm

3.2.2. BLE Performance: Transmitter Characteristics

Table 22. Transmit (TX) Characteristics – Bluetooth

Parameter	Test Condition	TYP	Unit
Output power	Conducted output from ANT pin of the module, 5dBm setting	3.1	dBm
	Conducted output from ANT pin of the module, 4dBm setting	1.8	
	Conducted output from ANT pin of the module, 3dBm setting	0.9	
	Conducted output from ANT pin of the module, 2dBm setting	0.2	
	Conducted output from ANT pin of the module, 1dBm setting	-0.7	
	Conducted output from ANT pin of the module, 0dBm setting	-1.8	
Output power programmable range	Conducted output from ANT pin of the module	26	dB

3.2.3. Zigbee Performance: Receiver Characteristics

Table 23. Receiver (RX) Characteristics – Zigbee Performance

Parameter	Test Condition	TYP	Unit
Receiver sensitivity	Coherent mode PER = 1%	-104	dBm
Receiver saturation	PER = 1%	> -10	dBm
Adjacent channel rejection	Wanted signal at -82 dBm, modulated interferer at ± 5 MHz, PER = 1%	36	dB
Adjacent channel rejection	Wanted signal at -82 dBm, modulated interferer at ± 10 MHz, PER = 1%	55	dB
Channel rejection, ± 15 MHz or more	Wanted signal at -82 dBm, undesired signal is IEEE 802.15.4 modulated channel, stepped through all channels 2405 to 2480 MHz, PER = 1%	59	dB
Blocking and desensitization, 5 MHz from upper band edge	Wanted signal at -97 dBm (3 dB above the sensitivity level), CW jammer, PER = 1%	57	dB
Blocking and desensitization, 10 MHz from upper band edge	Wanted signal at -97 dBm (3 dB above the sensitivity level), CW jammer, PER = 1%	62	dB

Parameter	Test Condition	TYP	Unit
Blocking and desensitization, 20 MHz from upper band edge	Wanted signal at -97 dBm (3 dB above the sensitivity level), CW jammer, PER = 1%	62	dB
Blocking and desensitization, 50 MHz from upper band edge	Wanted signal at -97 dBm (3 dB above the sensitivity level), CW jammer, PER = 1%	65	dB
Blocking and desensitization, -5 MHz from lower band edge	Wanted signal at -97 dBm (3 dB above the sensitivity level), CW jammer, PER = 1%	60	dB
Blocking and desensitization, -10 MHz from lower band edge	Wanted signal at -97 dBm (3 dB above the sensitivity level), CW jammer, PER = 1%	60	dB
Blocking and desensitization, -20 MHz from lower band edge	Wanted signal at -97 dBm (3 dB above the sensitivity level), CW jammer, PER = 1%	60	dB
Blocking and desensitization, -50 MHz from lower band edge	Wanted signal at -97 dBm (3 dB above the sensitivity level), CW jammer, PER = 1%	62	dB
Spurious emissions, 30 MHz to 1000 MHz	Measurement in a 50 Ω single-ended load	-66	dBm
Spurious emissions, 1 GHz to 12.75 GHz	Measurement in a 50 Ω single-ended load	-53	dBm
Frequency error tolerance	Difference between the incoming carrier frequency and the internally generated carrier frequency	> 100	ppm
Symbol rate error tolerance	Difference between incoming symbol rate and the internally generated symbol rate	> 800	ppm
RSSI dynamic range		95	dB
RSSI accuracy		± 4	dB

3.2.4. Zigbee Performance: Transmitter Characteristics

Table 24. Transmit (TX) Characteristics – Zigbee Performance

Parameter	Test Condition	TYP	Unit
Max output power, 5 dBm setting	Differential mode, delivered to a single-ended 50 Ω load through a balun	3	dBm
Output power programmable range	Conducted output from ANT pin of the module	26	dB

3.3. Antenna Characteristics

The module series has different variants for antenna selection. BDE-MP2674R10A variant has integrated a 2.4GHz PCB trace antenna which makes it a good choice for easy integration. The antenna area is 15 mm x 3.8 mm, refer to [Figure 7](#). The following data was measured with the module assembled to a reference board. The module placement and the dimension of the reference board is shown in below figure.

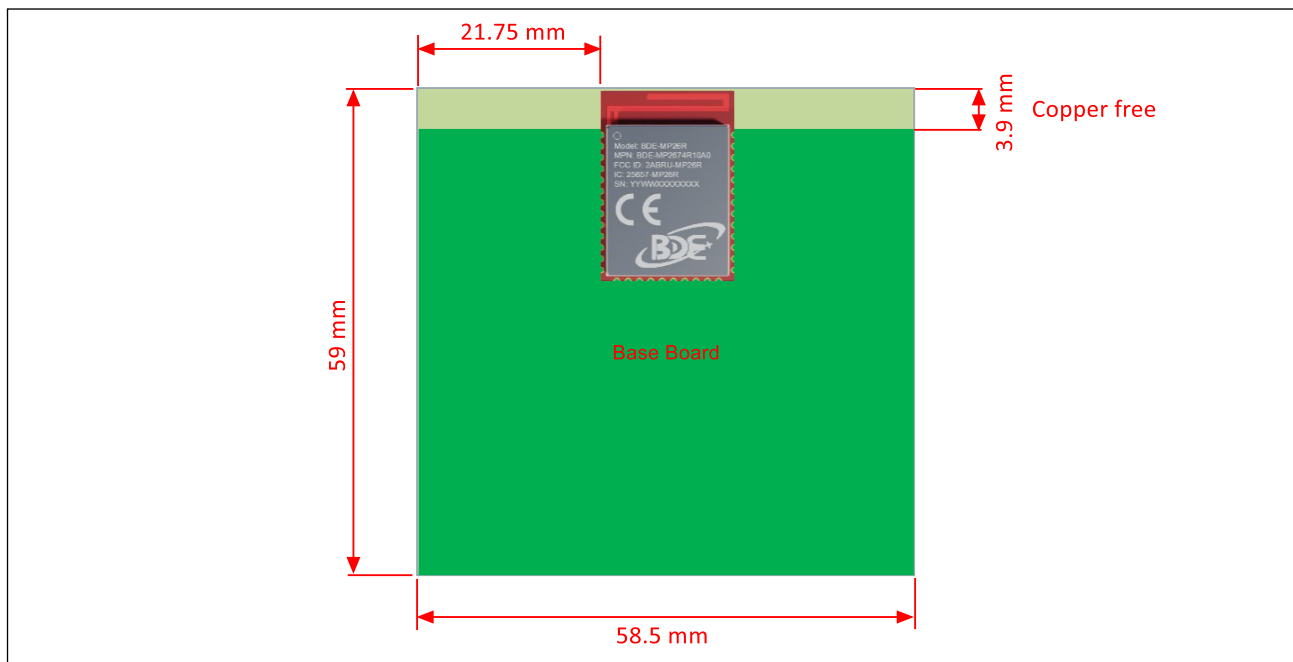


Figure 7. Antenna Placement and Reference Board

3.3.1. Antenna Gain

Table 25. Gain of Integrated PCB Trace Antenna

Frequency (MHz)	Gain (dBi)
2400	-1.75
2410	-1.66
2420	-1.50
2430	-1.32
2440	-1.10
2450	-0.88
2460	-0.84
2470	-1.13
2480	-1.51

3.3.2. Antenna Radiation Pattern

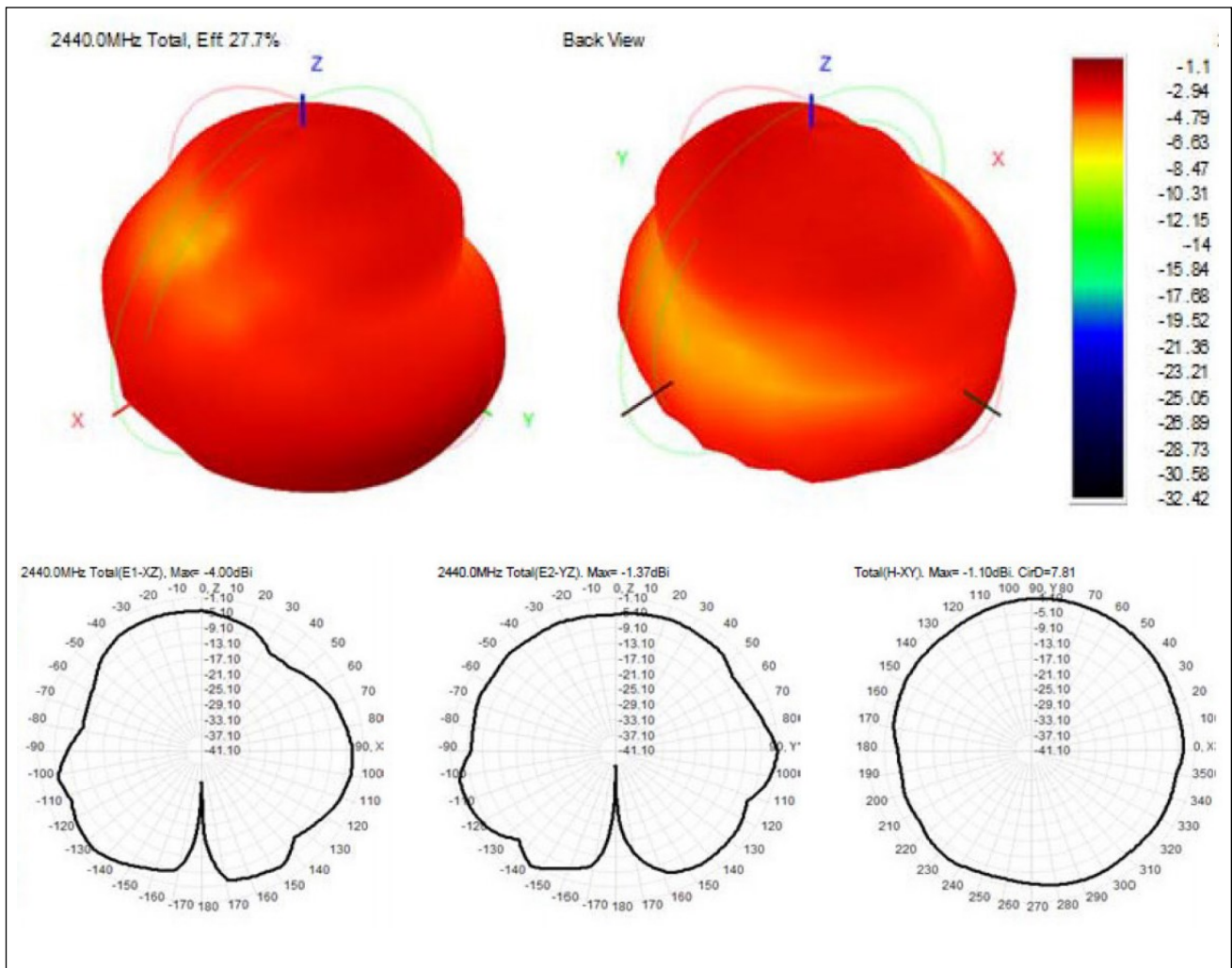


Figure 8. Radiation Pattern of the Integrated PCB Trace Antenna at 2440MHz

3.3.3. Other Certified Antennas

For other certified antennas, please refer to [Table 30](#).

4. Mechanical Specifications

4.1. Dimensions

The following pages include mechanical, footprint drawings, and marking information.

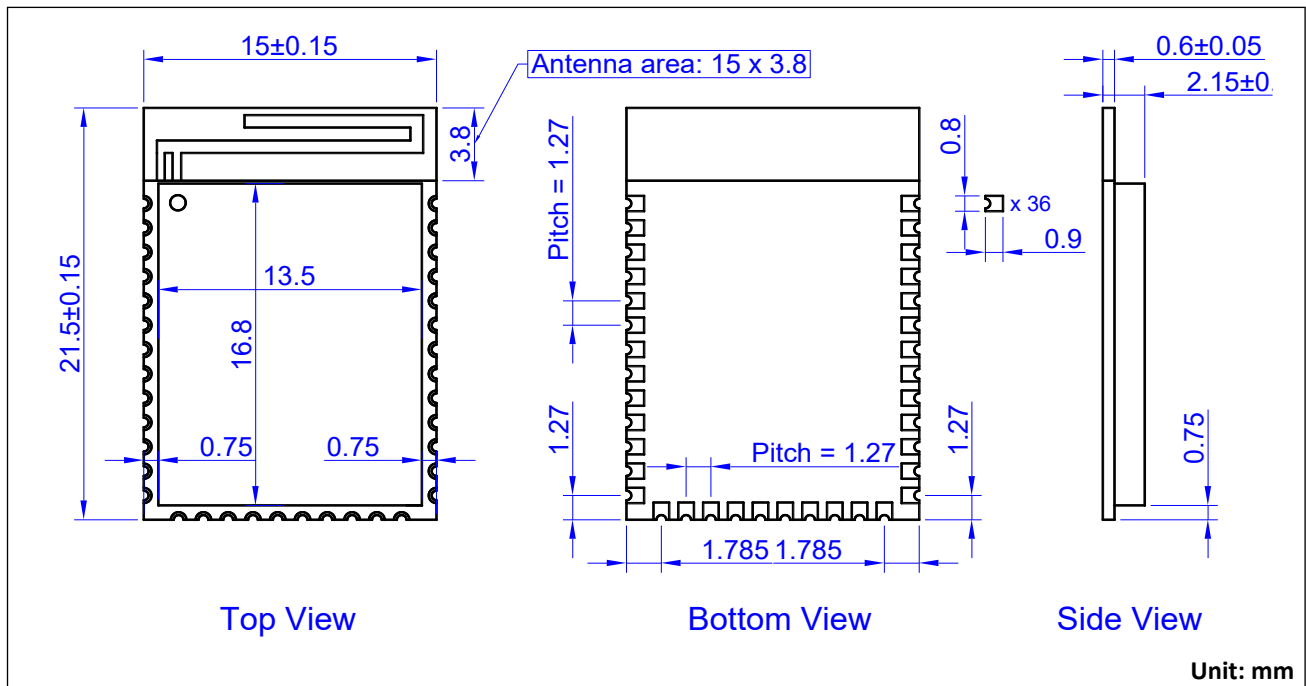


Figure 9. Mechanical Drawing of BDE-MP2674R10A

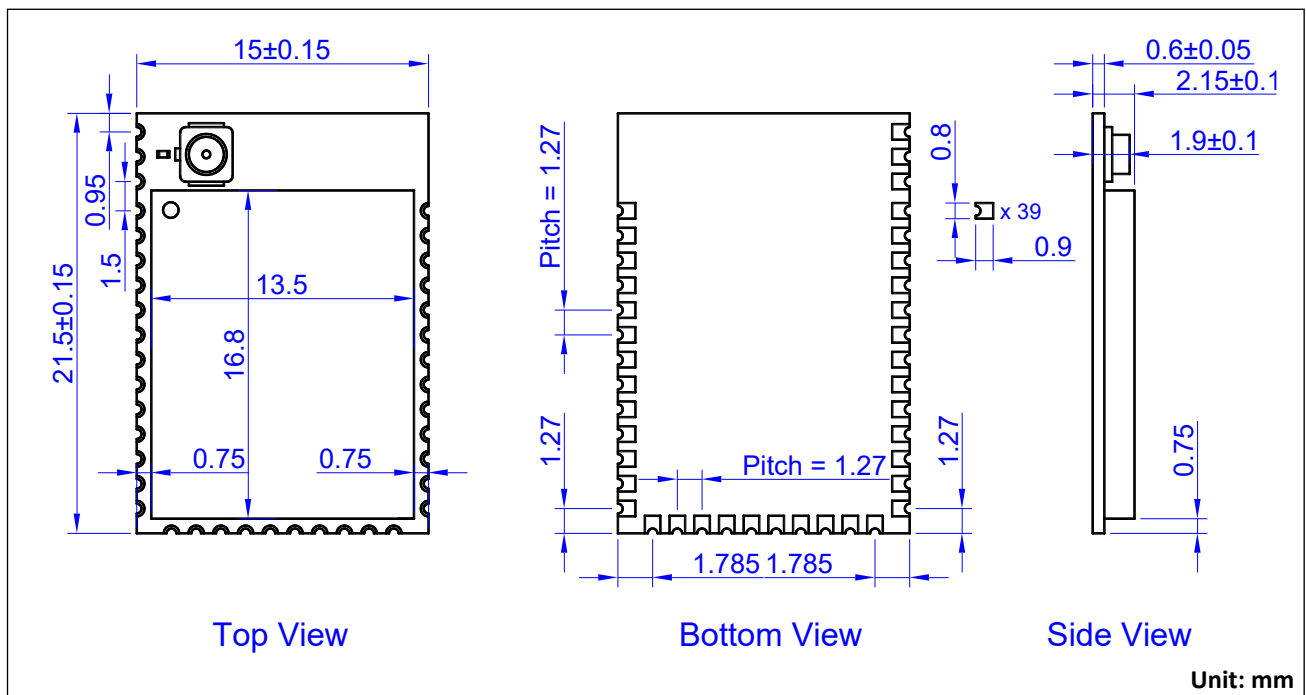


Figure 10. Mechanical Drawing of BDE-MP2674R10U and BDE-MP2674R10N

4.2. PCB Footprint

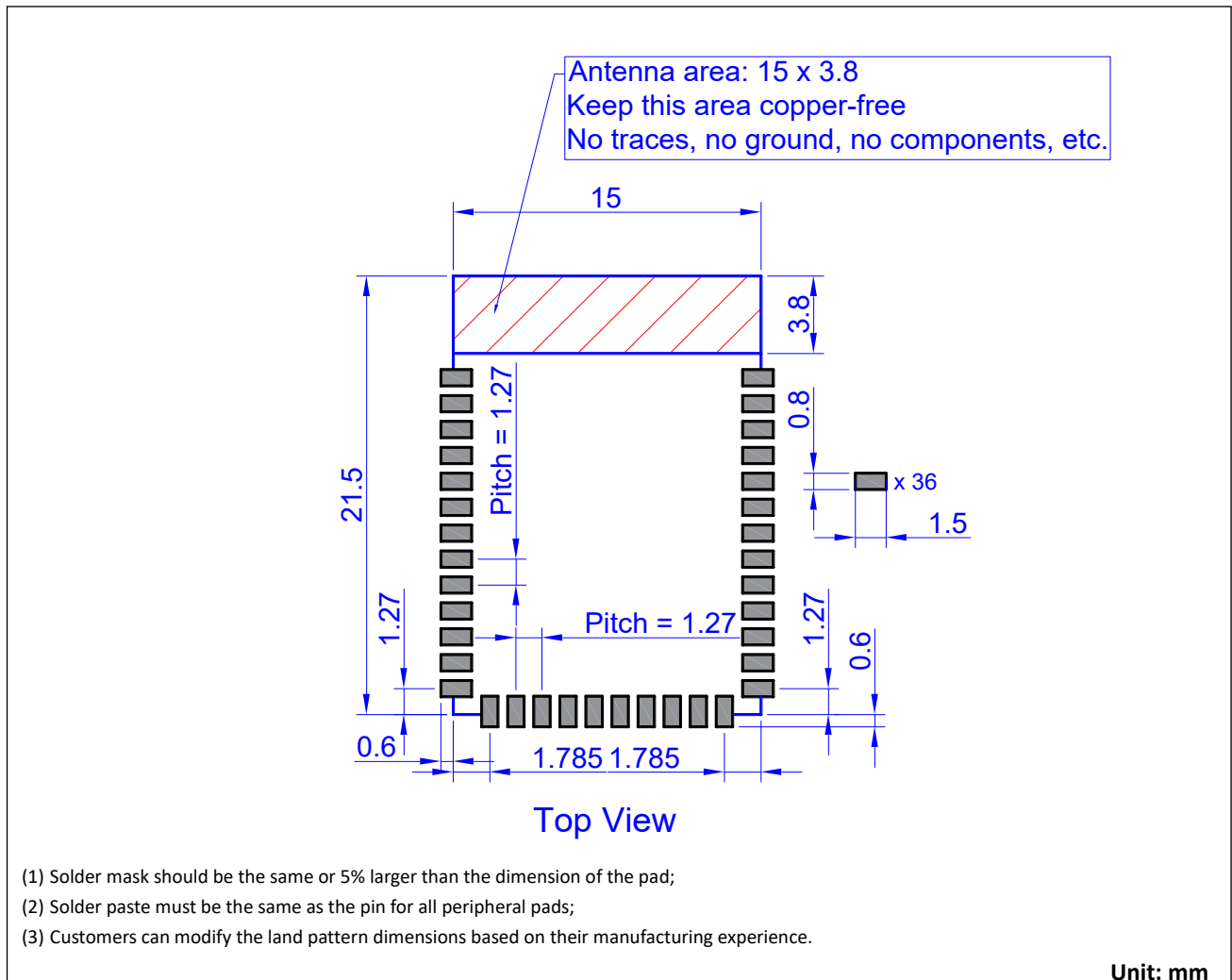
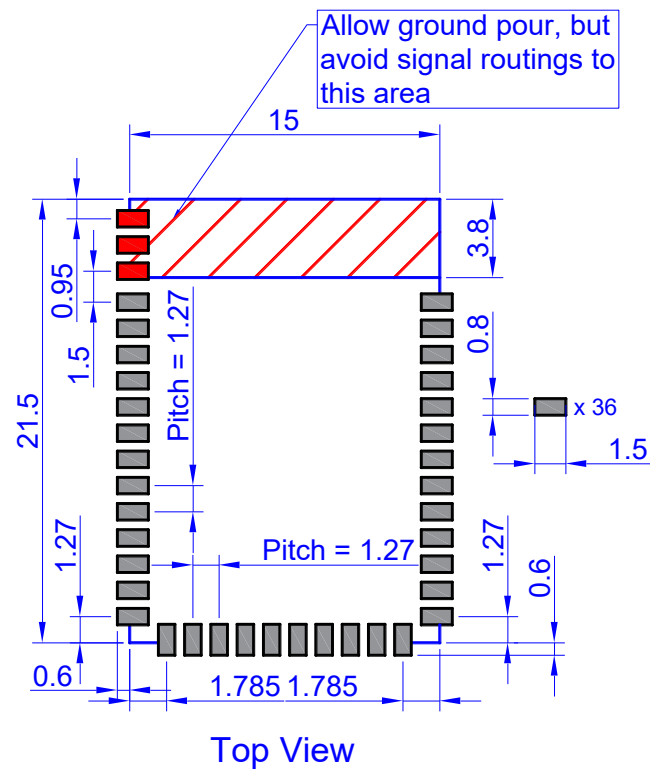


Figure 11. Recommended Module Footprint of BDE-MP2674R10A



- (1) Solder mask should be the same or 5% larger than the dimension of the pad;
- (2) Solder paste must be the same as the pin for all peripheral pads;
- (3) Customers can modify the land pattern dimensions based on their manufacturing experience;
- (4) Three pads with red fill are only for N variants, they can be unused for U variants.

Unit: mm

Figure 12. Recommended Module Footprint of BDE-MP2674R10U and BDE-MP2674R10N

4.3. U.FL Connector Specification

The drawing and specification of the U.FL connector utilized in the module is as below for reference.

The dimension unit in below drawing is millimeter.

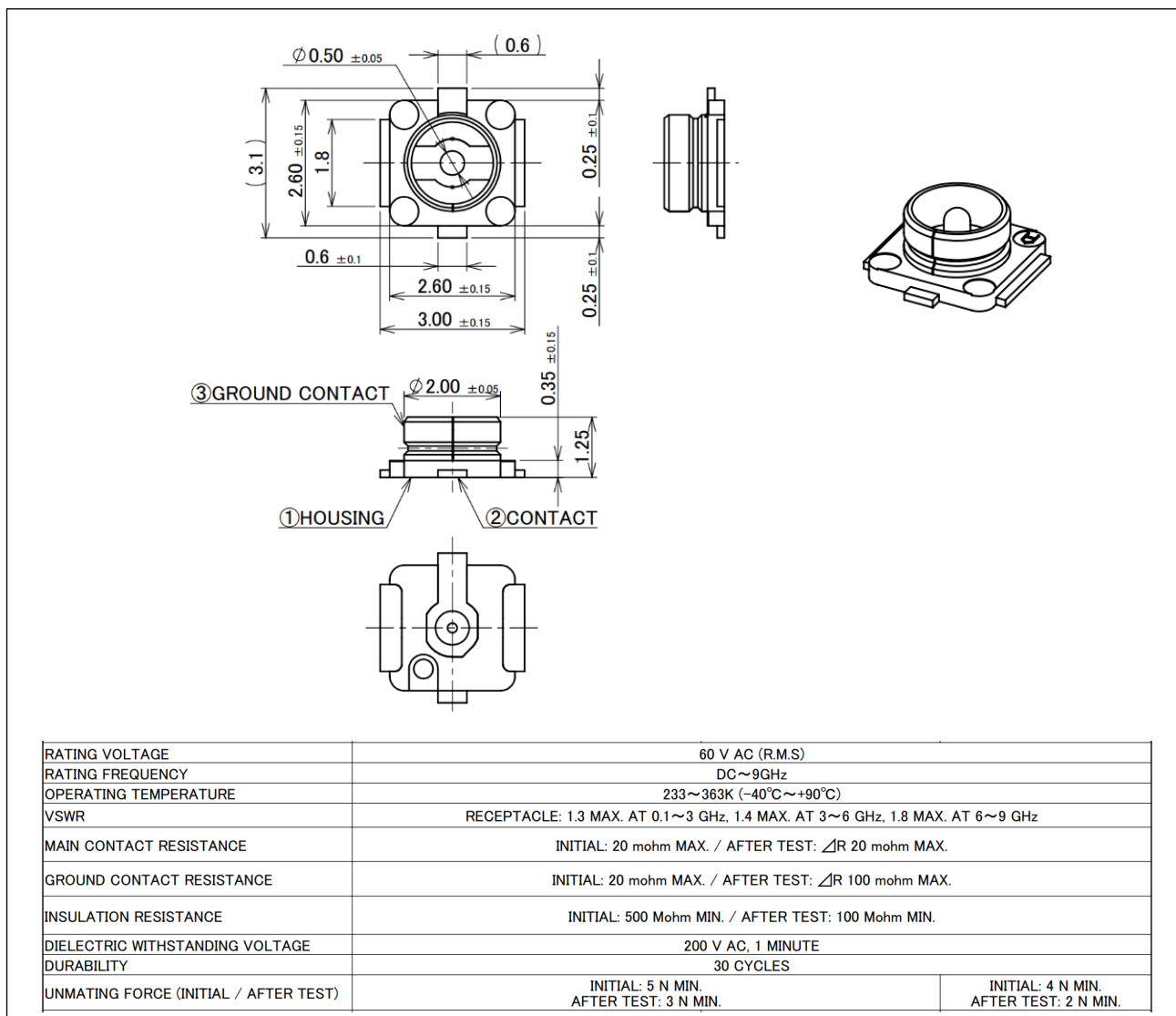


Figure 13. U.FL Connector Drawing and Specification

5. Integration Guidelines

5.1. SoC Mode

Below block diagram is applicable when the module is used as a SoC running the application and the protocol stack in the system CUP inside the module.

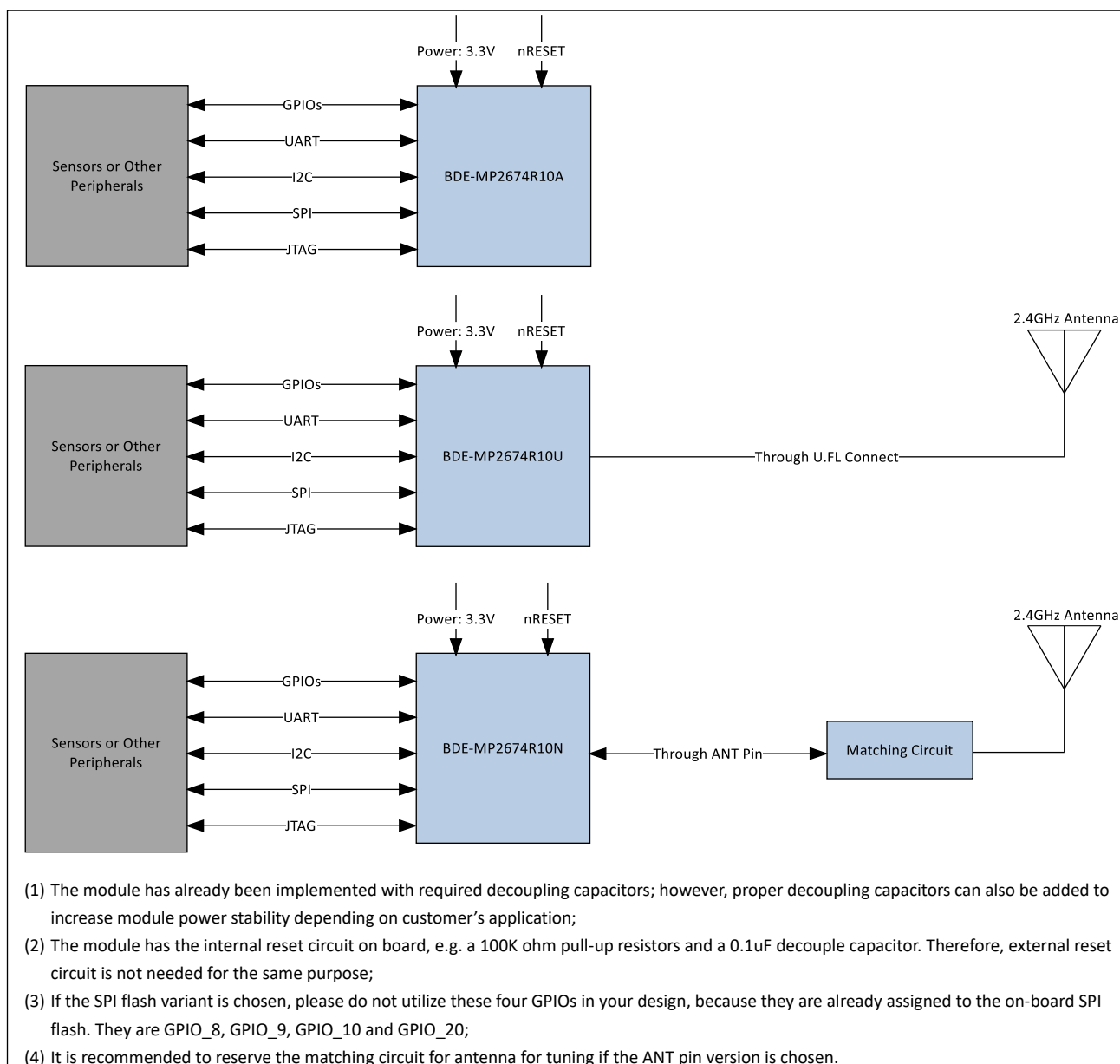


Figure 14. High-Level System Block Diagram

5.2. WNP Mode

The module can also function as the WNP (Wireless Network Processor), in this case, an external MCU will be needed to run the application and the protocol stack, and the interface between the external MCU and the module can be UART/SPI.

5.3. Module Placement

The placement of the module in the base board is critical in your design. Improper placement can lead to poor antenna performance. BDE recommend following below recommended placement in your design.

Any form of proximity to the metal or other material will change/degrade the antenna performance. Keep the antenna area as far as possible to the metal material in any direction.

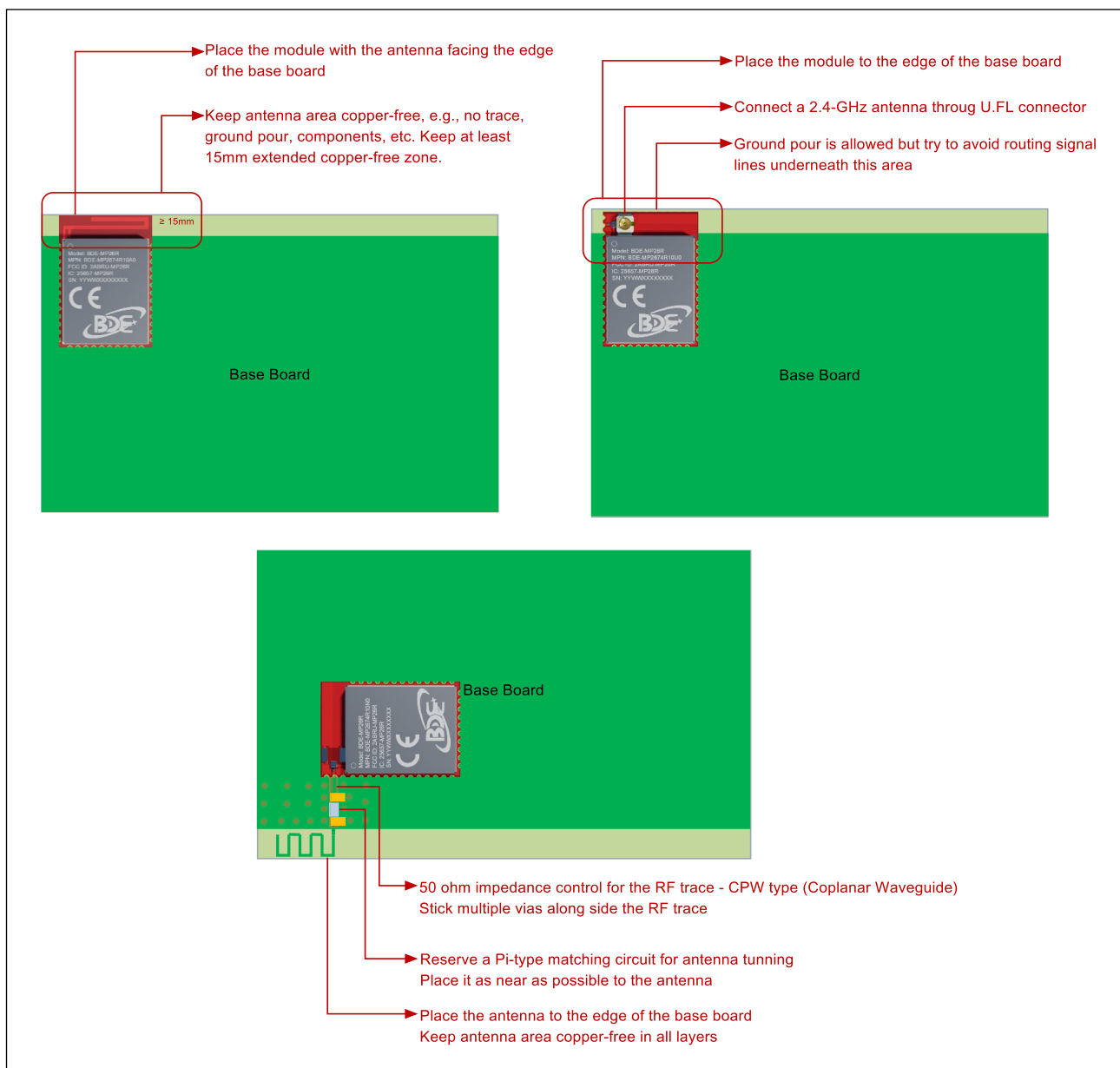


Figure 15. Module Placement Recommendations

5.4. Other Design Considerations

Table 26. Other Design Considerations

Thermal	
1	The proximity of ground vias must be close to each ground pad of the module.
2	Signal traces must not be run underneath the module on the layer where the module is mounted.
3	Have a complete ground pour in layer 2 for thermal dissipation.
4	Have a solid ground plane and ground vias under the module for stable system and thermal dissipation.
5	Increase the ground pour in the first layer and have all of the traces from the first layer on the inner layers, if possible.
6	Signal traces can be run on a third layer under the solid ground layer, which is below the module mounting layer.
RF Trace and Antenna Routing	
7	The RF trace antenna feed must be as short as possible beyond the ground reference. At this point, the trace starts to radiate.
8	The RF trace bends must be gradual with an approximate maximum bend of 45° with trace mitered. RF traces must not have sharp corners.
9	RF traces must have via stitching on the ground plane beside the RF trace on both sides.
10	RF traces must have constant impedance (50-ohm Coplanar or microstrip transmission line).
11	For best results, the RF trace ground layer must be the ground layer immediately below the RF trace. The ground layer must be solid.
12	There must be no traces or ground under the antenna section.
13	RF traces must be as short as possible. The antenna, RF traces, and modules must be on the edge of the PCB product. The proximity of the antenna to the enclosure and the enclosure material must also be considered.
14	BDE recommends using double-shielded coaxial RF cable to connect with the U.FL connector with antenna if the U.FL variants are selected.
15	Do not place or run the RF cable right above or below the module.
16	If there are some other radios besides this module in the system, try to place them apart as far as possible. And ensure there is at least 25 dB isolation between the antenna port of every radio.
Supply and Interface	
17	Make VDD traces as wide as possible to ensure reduced inductance and trace resistance.
19	If possible, shield VDD traces with ground above, below, and beside the traces.

5.1. Development Resources

For more information on the EVK or other development resources, please visit the product page of the module on bdecomm.com.

6. Handling Instructions

The module is the surface mount module with LCC footprint. It is designed to conform to the major manufacturing guidelines, including the commercial, industrial manufacturing process.

In this section, we will cover the basic shipping information, including the module markings, packaging and labeling. And also, the instructions on how to handle the module in terms of storage, assembly and so on.

6.1. Module Marking

Below figure shows the metal shield marking for the BDE-MP2674R10 module series.

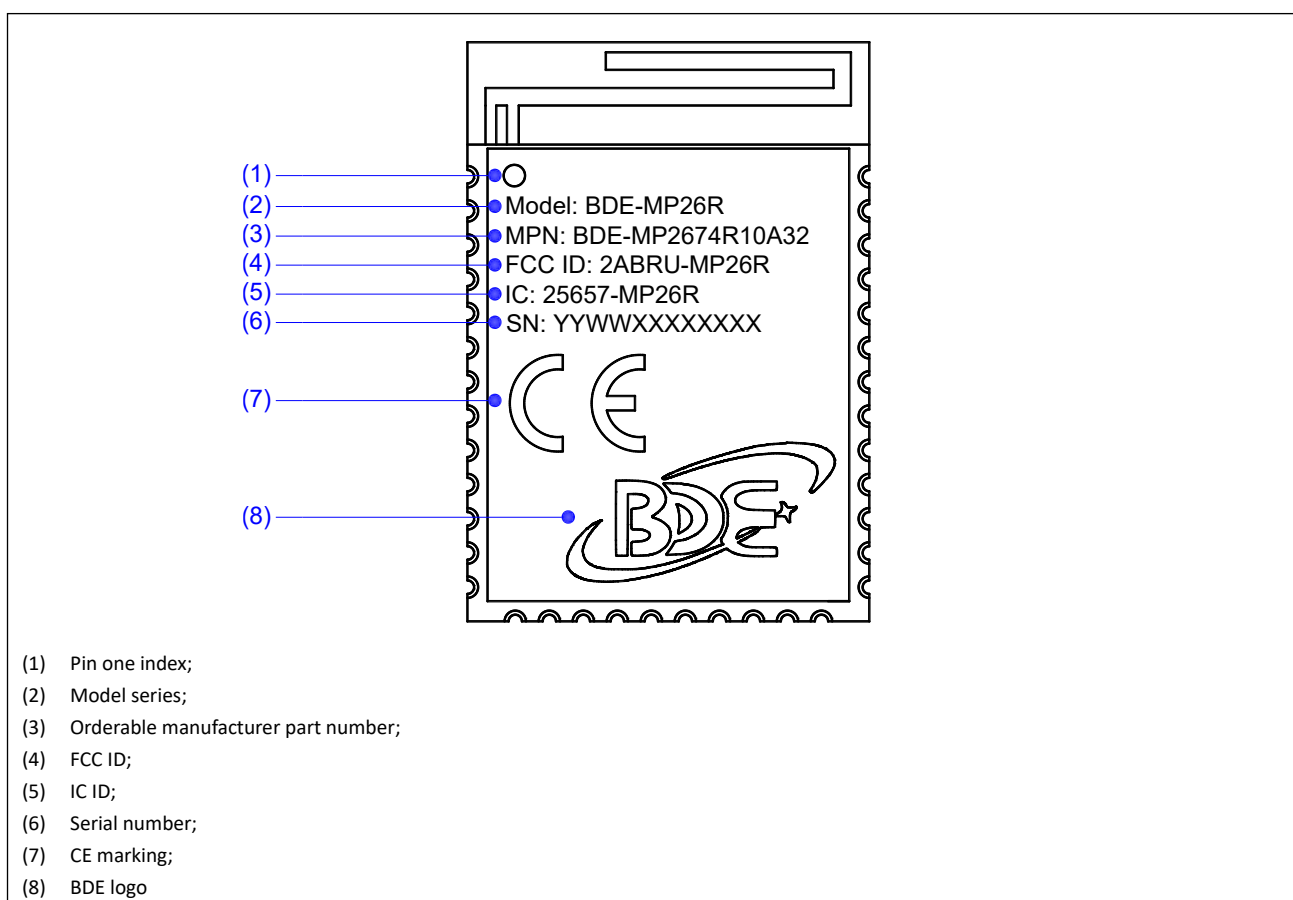


Figure 16. Module Marking

6.2. Packaging Information

6.2.1. Tape and Reel Package Information

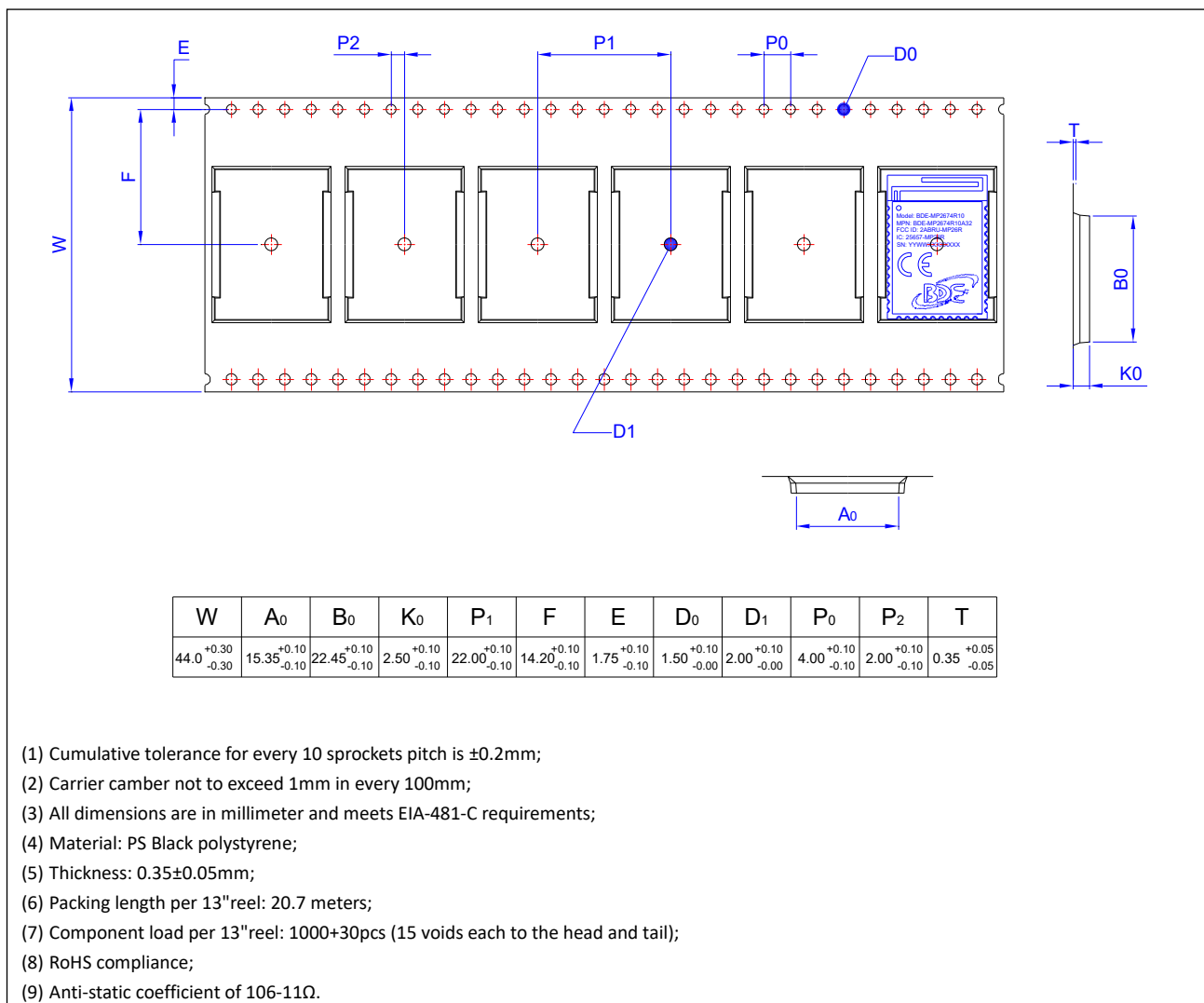


Figure 17. Carrier Tape Drawing for BDE-MP2674R10 variants

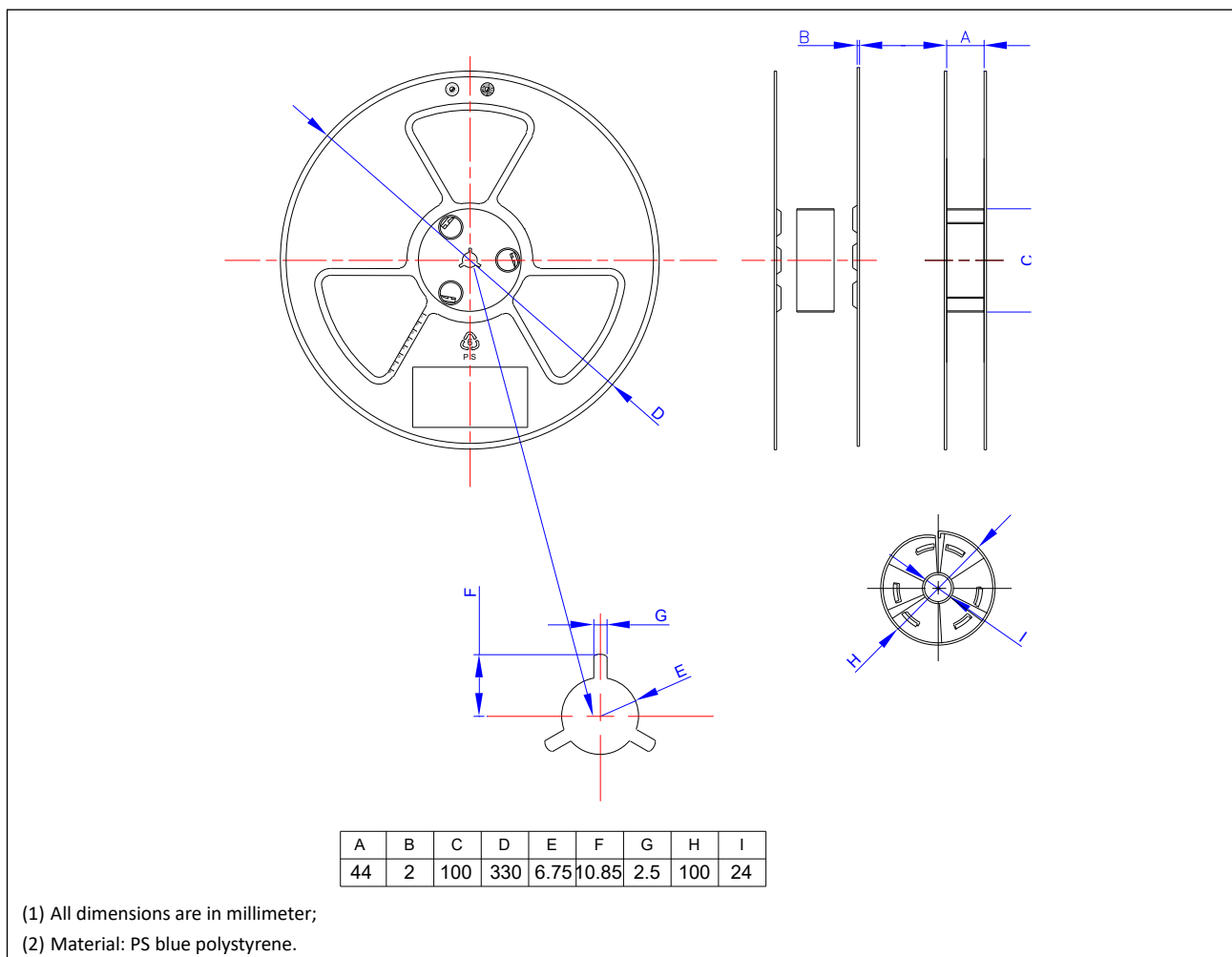


Figure 18. 13-INch Reel Drawing

6.2.2. Carton Information and Labeling

6.2.2.1. Carton Information

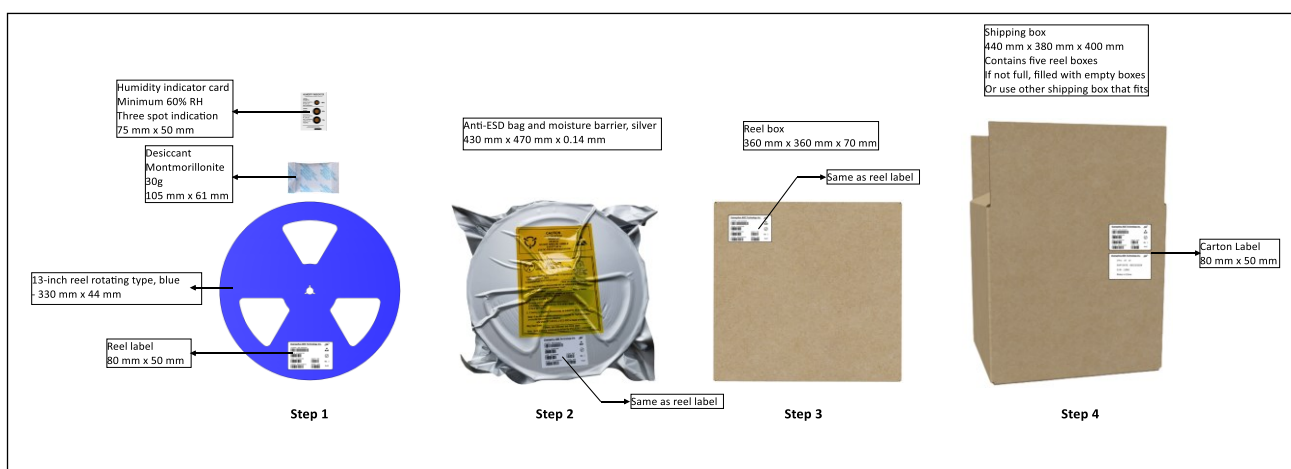


Figure 19. Carton Information

6.2.2.2. Reel Label

The reel label will be affixed onto the reel, Anti-ESD bag and reel box. It mainly shows the MPN (Manufacturer Part Number), CPN (Customer Part Number), PO (Purchase Order Number), LOT number, QTY (Quantity), DC (Date Code) and MSL (Moisture Sensitivity Level). Sometimes, it also shows other information, such as the regulatory information.

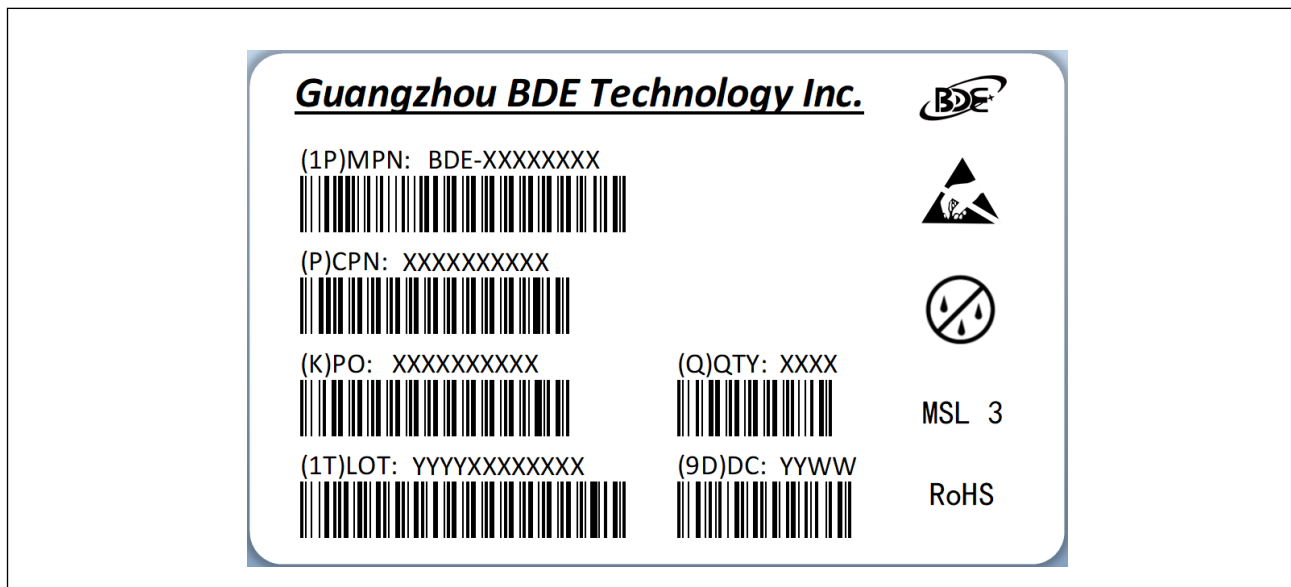


Figure 20. Reel Label Information

6.2.2.3. Carton Label

The carton label will be affixed onto the surface of the carton. If the carton contains different Part Numbers or POs, there will be different labels representing different Part Numbers, different POs and Quantity.

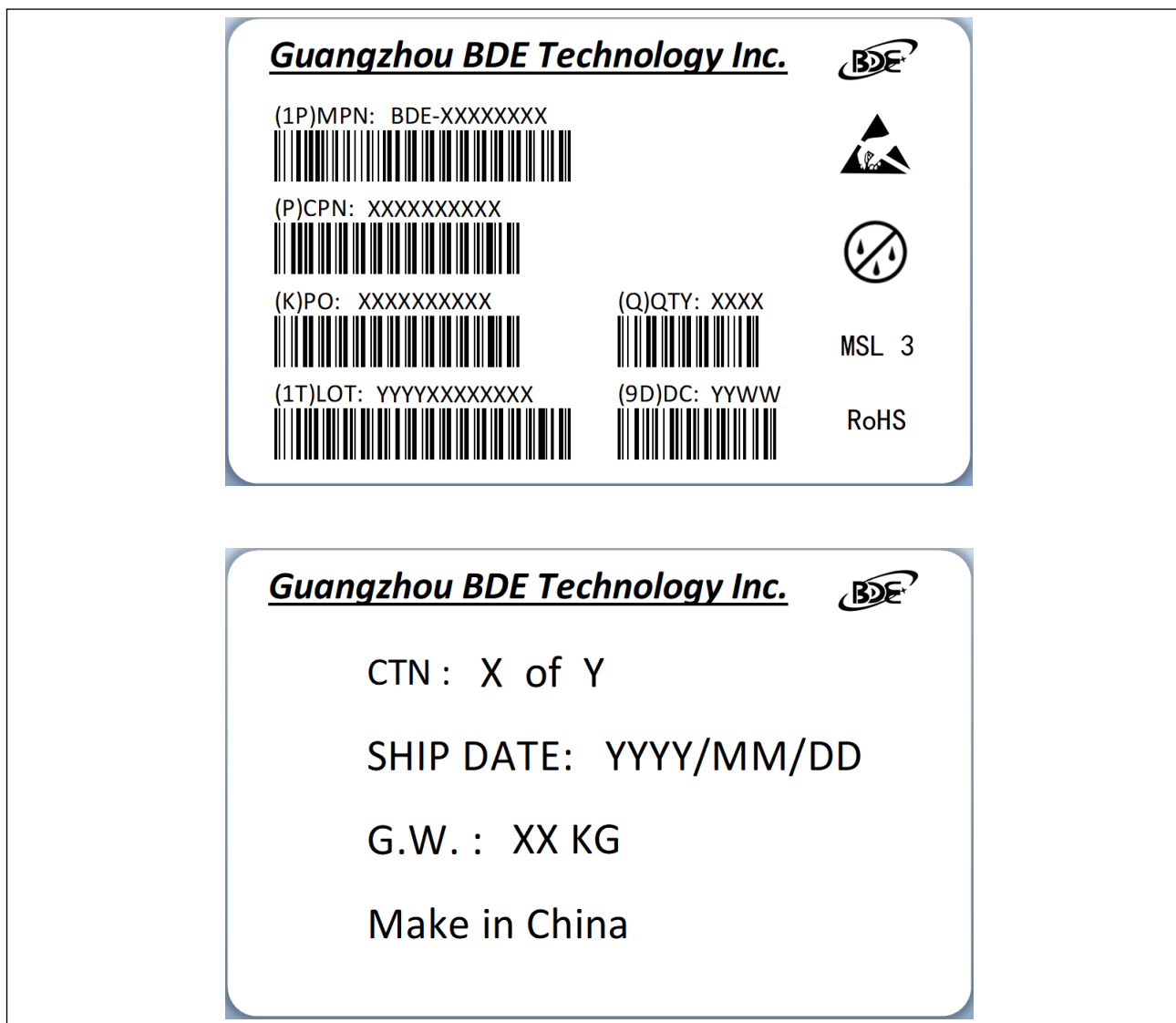


Figure 21. Carton Label Information

6.3. Assembly Instruction

6.3.1. Moisture Sensitive Level

The MSL (Moisture Sensitive Level) of the module is MSL-3. Handling guidelines are listed as below:

The floor life for MSL-3 device is 168 hours in ambient environment 30°C/60%RH. Before assembly, make sure to check if the modules are packaged with desiccant and humidity indicator card;

After the bag is opened, make sure to mount the modules within 168 hours at factory conditions (< 30°C/60% RH) or stored at <10% RH. Repackage is needed with new desiccant and humidity indicator card if the modules are not mounted before exceeding floor life;

If the card reads >10%, or the modules have been exposed for over 168 hours, the modules need to be baked before mounted. Recommended baking condition is 125°C for 8 hours.

6.3.2. Reflow Profile

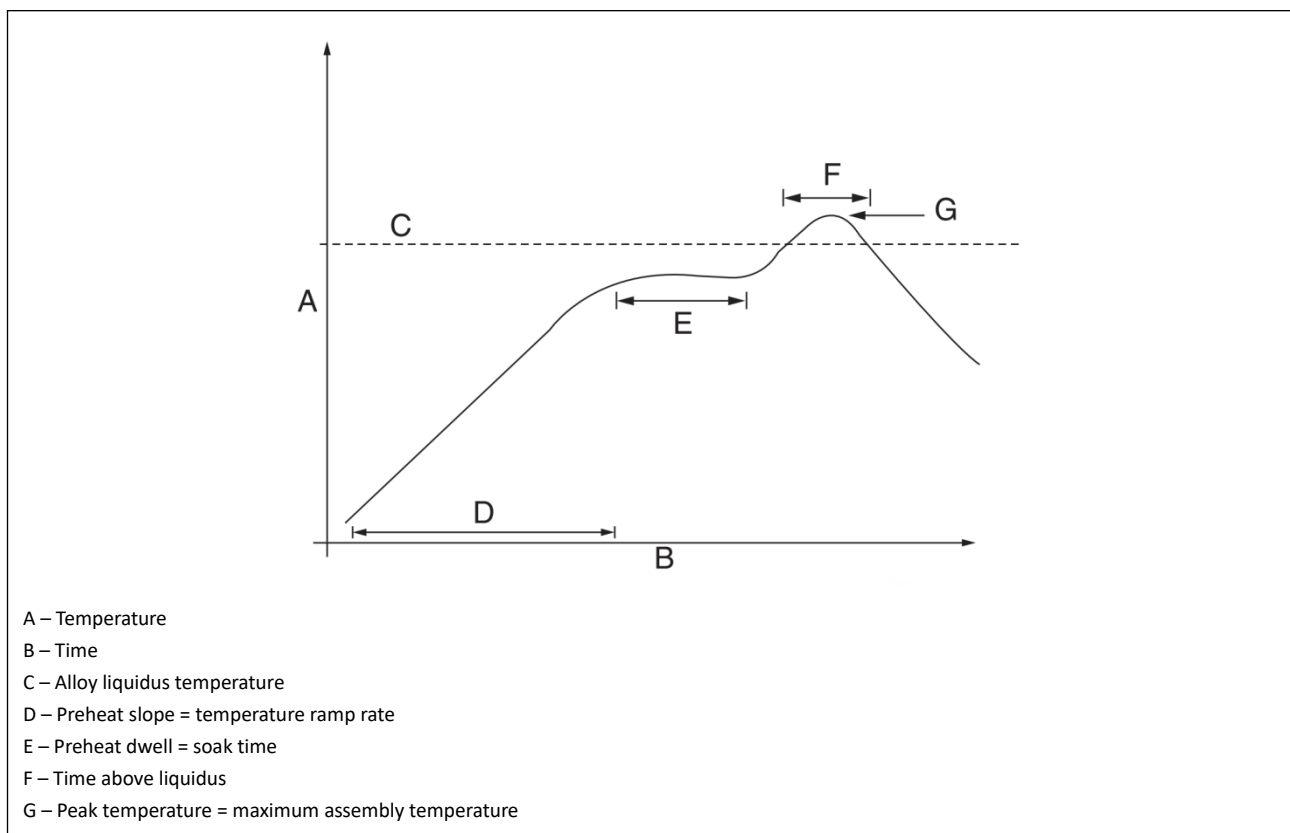


Figure 22. Thermal Profile Schematic

Table 27. Reflow Profile Parameters^{(1) (3)}

Item	Temperature Range	Ramp Rate / Time
D, preheat zone	30°C ~ 175°C	2°C ~ 4°C per second
E, soak zone	150°C ~ 200°C	60 ~ 120 seconds
C, Alloy liquidus temperature	217°C ~ 220°C	-
F, reflow zone	230°C ~ 245°C	60 ~ 90 seconds
G, target maximum reflow temperature	250°C	-
Absolute peak temperature ⁽²⁾	260°C	-

(1) This is for Pb-free (SAC 305) paste. Different pastes require different profiles for optimum performance, so it is important to consult the paste manufacturer before developing the solder profile;

(2) Exceed the absolute peak temperature for certain period, e.g. 20s might damage the device or affect the reliability;

(3) It is recommend that the modules do not go through the reflow process more than one time.

6.3.3. Other Consideration

- (1) Ultrasonic cleaning process is discouraged for the modules as the process might damage the module permanently, especially for the crystal oscillator in the module;
- (2) Conformal coating is not allowed to this module. It will impact the reliability of the module once the coating flooded into the shield. Avoid the module while applying the conformal coating to the host board.

7. Certification

7.1. Bluetooth Qualification

7.1.1. Bluetooth Qualification Information

The module series is listed on the Bluetooth SIG website as a qualified End Product with below information in the table.

Table 28. Bluetooth Qualification Information

DID/DN	QDID and Included DN
D058375	199566

7.1.2. Bluetooth Qualification Process

Below Bluetooth qualification process is provided for customers when they are listing their end product referencing BDE module.

- (1) Go to <https://launchstudio.bluetooth.com/> and log in;
- (2) Select **Start the Bluetooth Qualification Process with No Required Testing**;
- (3) Project Basics:
 - (a) Enter your project name, it can be the product name or the product series name;
 - (b) Enter QDID that the product reference, in this case the QDID is 199566.
- (4) Product Declaration:
 - (a) Select the listing date. You can select a date that you want your product listed and go public, although the qualification will complete immediately after your submission.
 - (b) Add every product that integrated with this module. You can add a series of individual product models that use the same design/module without any modification.
- (5) Declaration ID:
 - (a) Select a DID. If you don't have one, you need to purchase a DID for your product by clicking Pay Declaration Fee.
- (6) Review and Submit:
 - (a) Review all information that you have entered and make sure no mistakes;
 - (b) Tick all check boxes if you confirmed above information and add your name to the signature page;
 - (c) Click **Signature Confirmed – Complete Project & Submit Product(s) for Qualification**.
- (7) The qualification will be done immediately and your product will be listed to the Bluetooth SIG website as per your required listed date in step (4).

For more information about listing your product to Bluetooth SIG, please visit below webpage:

<https://www.bluetooth.com/develop-with-bluetooth/qualification-listing/>

7.2. Regulatory Compliance

The module is certified for FCC, IC/ISED and ETSI/CE as listed in below table. More regions can be cover by request.

Table 29. Certification Information

Regulatory Body / Region	Standard	ID	MPN
FCC (USA)	FCC CFR 47 PART 15 C (15.247)	2ABUR-MP26R	BDE-MP2674R10A0
IC/ISED (Canada)	RSS-247 Issue 3	25657-MP26R	BDE-MP2674R10A32
	RSS-Gen Issue 5		BDE-MP2674R10U0
	ANSI C63.10: 2013		BDE-MP2674R10U32
ETSI/CE-RED (Europe)	ETSI EN 301 489-1 V2.2.3 (2019-11)	NA	BDE-MP2674R10N0
	ETSI EN 301 489-17 V3.3.1 (2024-09)		BDE-MP2674R10N32
	EN 55032:2015/A11:2020		BDE-MP2674R10A0-IN
	EN 55035:2017/A11:2020		BDE-MP2674R10A32-IN
	ETSI EN 300 328 V2.2.2 (2019-07)		BDE-MP2674R10U0-IN
	EN 62479:2010		BDE-MP2674R10U32-IN
	EN 50663:2017		BDE-MP2674R10N0-IN
	EN IEC 62368-1:2020+A11:2020		BDE-MP2674R10N32-IN

7.2.1. Certified Antennas

The module series has been tested and certified with three antennas, where BDE-MP2674R10A variants utilize an integrated PCB trace antenna, BDE-MP2674R10U variants utilize an external 2.4GHz whip antenna through U.FL connector, BDE-MP2674R10N utilize an external 2.4GHz whip antenna utilized in the evaluation board through the dedicated ANT pin of the module.

The characteristic of the antennas is listed in below. The PCB trace antenna is only present in the BDE-MP2674R10A.

Table 30. Certified Antenna List

Antenna Type	Manufacturer	MPN	Frequency Range (MHz)	Peak Gain (dBi)	Note
PCB trace antenna	BDE	BDE-ANT-MB26RA	2400 – 2500	-0.84	Internal
Whip antenna	BDE	BDE-W25-19513-HRP	2400 – 2500	3.0	External

Customers are encouraged to use the certified antennas in the case of external antenna options to reduce certification testing effort and risk of failing. If customer want to choose another antenna that fits their product, there are some scenarios that need to be considered.

If the external antenna is of the same antenna type and of equal or less gain compared to the ones listed in above table, and with similar in-band and out-of-band characteristic, then the antenna can be used with the module in USA and Canada where modular approval is applicable, as long as the spot-check testing of the new antenna with host is performed to verified that it will not change the performance. However, in countries such as EU countries applying the ETSI standards where the modular approval is not applicable, the radiated emissions are always tested with the end product with any antennas.

If the external antenna is of a different type or with non-similar in-band and out-of-band characteristic, but still has equal gain or less gain compared to the above listed antennas. The new antenna can be added to the existing modular grant/certificate by filing a permissive change, C2PC (Class II Permissive Change) in case of FCC and ISSED. The radiated emission testing is needed, but re-certification is not required.

In the case of the external antenna with higher gain than the peak gain listed in above table are very likely to require a

full new end product certification. However, we recommended that you consult with your certification house to understand the correct approaches for your product case by case.

7.2.2. FCC Compliance

7.2.2.1. FCC Statement

This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and,
- (2) This device must accept any interference received, including interference that may cause undesired operation.

7.2.2.2. FCC Caution

Any changes or modifications to this unit not expressly approved by BDE for compliance could void the user's authority to operate the equipment. The integrator will be responsible to satisfy SAR/RF Exposure requirements, when the module integrated into the host device.

7.2.2.3. Integration Instructions

List of applicable FCC rules

FCC Part 15.247

Specific operational use conditions

This transmitter/module and its antenna(s) must not be co-located or operating in conjunction with any transmitter. This information also extends to the host manufacturer's instruction manual.

Limited module procedures

Not applicable

Trace antenna designs

Not applicable

RF exposure considerations

This equipment complies with FCC RF radiation exposure limits set forth for an uncontrolled environment. This compliance to FCC radiation exposure limits for an uncontrolled environment, and minimum of 20cm separation between antenna and body. The host product manufacturer would provide the above information to end users in their end-product manuals.

Antennas

Refer to [Table 30](#)

Label and compliance information

The end product must carry a physical label or shall use e-labeling followed KDB784748D01 and KDB784748 stating "Contains Transmitter Module FCC ID: 2ABRU-MP26R"

Information on test modes and additional testing requirements

Contact BDE for more information

Additional testing, Part 15 Subpart B disclaimer

The modular transmitter is only FCC authorized for the specific rule parts (FCC Part 15.247) listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. The final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed when contains digital circuitry.

(OEM) Integrator has to assure compliance of the entire end-product that includes the BDE-MP2674R10 module. For 15 B (§15.107 and if applicable §15.109) compliance, the host manufacturer is required to show compliance with 15 while the module is installed and operating.

Furthermore the module should be transmitting and the evaluation should confirm that the module's intentional emissions (15C) are compliant (fundamental / out-of-band). Finally the integrator has to apply the appropriate equipment authorization (e.g. Verification) for the new host device per definition in §15.101. Integrator is reminded to assure that these installation instructions will not be made available to the end-user of the final host device.

7.2.3. IC/ISED Compliance

7.2.3.1. IC Statement

This device contains license-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's license-exempt RSS(s). Operation is subject to the following two conditions:

- (1) This device may not cause interference, and,
- (2) This device must accept any interference, including interference that may cause undesired operation of the device.

L'émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d'Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

- (1) L'appareil ne doit pas produire de brouillage;
- (2) L'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

7.2.3.2. IC Caution

Any changes or modifications to this unit not expressly approved by BDE for compliance could void the user's authority to operate the equipment. The integrator will be responsible to satisfy SAR/RF Exposure requirements, when the module integrated into the host device.

7.2.3.3. Integration Instructions

Label and compliance information

The final host device, into which this RF module is integrated has to be labeled with an auxiliary label stating the IC of the RF module, such as "Contains transmitter module IC: 25657-MP26R".

Informations sur l'étiquette et la conformité

Le périphérique hôte final, dans lequel ce module RF est intégré "doit être étiqueté avec une étiquette auxiliaire indiquant le CI du module RF, tel que "Contient le module émetteur IC: 25657-MP26R".

Radio Frequency Exposure Statement for IC

The device has been evaluated to meet general RF exposure requirements. The device can be used in mobile exposure conditions. The min separation distance is 20cm.

Déclaration d'exposition aux radiofréquences pour IC

L'appareil a été évalué pour répondre aux exigences générales en matière d'exposition aux RF. L'appareil peut être utilisé dans des conditions d'exposition mobiles. La distance de séparation minimale est de 20 cm.

This radio transmitter [IC: 25657-MP26R] has been approved by Innovation, Science and Economic Development Canada to operate with the antenna types listed in [Table 30](#), with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Cet émetteur radio [IC: 25657-MP26R] a été approuvé par Innovation, Sciences et Développement économique Canada pour fonctionner avec les types d'antenne énumérés ci-dessous, avec le gain maximal admissible indiqué. Les types d'antenne non inclus dans cette liste qui ont un gain supérieur au gain maximum indiqué pour tout type répertorié sont strictement interdits pour une utilisation avec cet appareil.

7.2.4. ETSI/CE Compliance

The BDE-MP2674R10 module is certified with required EU radio and EMC directives. See

[Table 29](#) for detailed standards the module complies with, or refer to UK Declaration of Conformity.

8. Ordering Information

Table 31. Ordering Information

Orderable Part Number	Description	Size (mm)	Shipping Form	MOQ
BDE-MP2674R10A32	BDE 2.4GHz multiprotocol wireless module, with PCB trace antenna, with on-board 32Mbit SPI flash, -40°C to +85°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10U32	BDE 2.4GHz multiprotocol wireless module, with U.FL connector, with on-board 32Mbit SPI flash, -40°C to +85°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10N32	BDE 2.4GHz multiprotocol wireless module, with ANT pin, with on-board 32Mbit SPI flash, -40°C to +85°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10A0	BDE 2.4GHz multiprotocol wireless module, with PCB trace antenna, -40°C to +85°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10U0	BDE 2.4GHz multiprotocol wireless module, with U.FL connector, -40°C to +85°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10N0	BDE 2.4GHz multiprotocol wireless module, with ANT pin, -40°C to +85°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10A32-IN	BDE 2.4GHz multiprotocol wireless module, with PCB trace antenna, with on-board 32Mbit SPI Flash, -40°C to +105°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10U32-IN	BDE 2.4GHz multiprotocol wireless module, with U.FL connector, with on-board 32Mbit SPI Flash, -40°C to +105°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10N32-IN	BDE 2.4GHz multiprotocol wireless module, with ANT pin, with on-board 32Mbit SPI Flash, -40°C to +105°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10A0-IN	BDE 2.4GHz multiprotocol wireless module, with PCB trace antenna, -40°C to +105°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10U0-IN	BDE 2.4GHz multiprotocol wireless module, with U.FL connector, -40°C to +105°C	21.5 × 15 × 2.15	Tape & Reel	1K
BDE-MP2674R10N0-IN	BDE 2.4GHz multiprotocol wireless module, with ANT pin, -40°C to +105°C	21.5 × 15 × 2.15	Tape & Reel	1K

9. Revision History

Table 32. Revision History

Revision	Date	Description
V0.1	12-October-2024	Preliminary, draft
V1.0	9-January-2025	Production release

Important Notice and Disclaimer

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